Universidad del País Vasco / Euskal Herriko Unibertsitatea

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ESCUELA DE INGENIERÍA DE BILBAO

INDUSTRIA INGENIARITZA TEKNIKOKO ATALA

SECCIÓN INGENIERÍA TÉCNICA INDUSTRIAL

INDUSTRIA ELEKTRONIKAREN ETA AUTOMATIKAREN INGENIERITZAKO GRADUA

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LANAREN IZENBURUA

ARDUINON OINARRITUTAKO ESTAZIO METEOROLOGIKO BATEN DISEINU, IMPLEMENTAZIO ETA KONTROLA

dokumentuaren izenburua

6. ERANSKINAK

IKASLEAREN DATUAK		**ZUZENDARIAREN DATUAK**	
IZENA	OIER	IZENA	MARIA GORETTI
ABIZENAK	AGUIRRE OROZCO	ABIZENAK	SEVILLANO BERASATEGUI
		SAILA	SISTEMEN INGENIERITZA ETA AUTOMATIKA
Sinadura		Sinadura	
DATA	2016-09-05	DATA	2016-09-05

II. eranskina

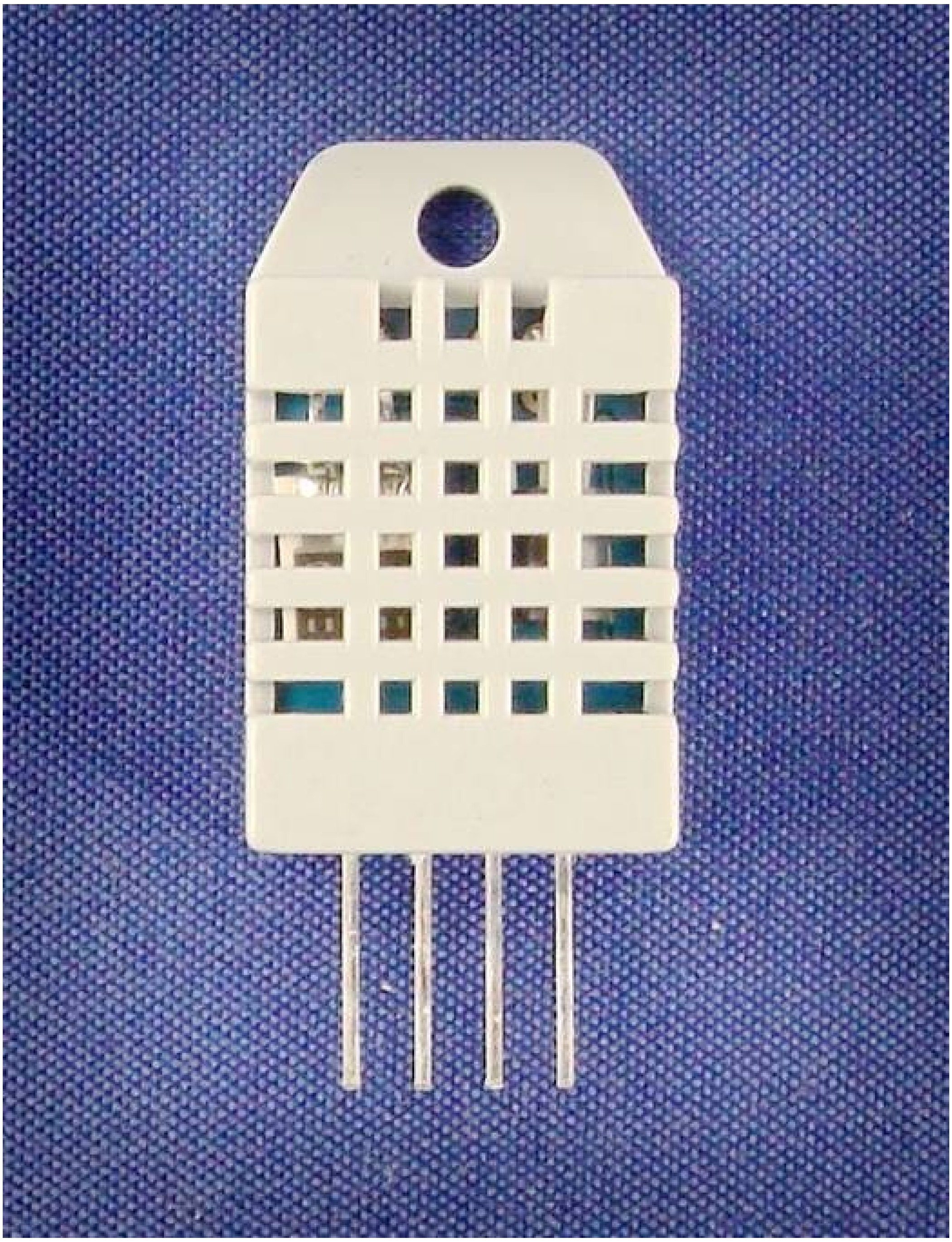
AURKIBIDEA

Aosong Electronics Co.,Ltd

Your specialist in innovating humidity & temperature sensors

Digital-output relative humidity & temperature sensor/module

DHT22 (DHT22 also named as AM2302)



Capacitive-type humidity and temperature module/sensor

Thomas Liu (Business Manager)

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Aosong Electronics Co.,Ltd

Your specialist in innovating humidity & temperature sensors

1. Feature & Application:

* Full range temperature compensated * Relative humidity and temperature measurement
* Calibrated digital signal *Outstanding long-term stability *Extra components not needed
* Long transmission distance * Low power consumption *4 pins packaged and fully interchangeable

2. Description:

DHT22 output calibrated digital signal. It utilizes exclusive digital-signal-collecting-technique and humidity sensing technology, assuring its reliability and stability.Its sensing elements is connected with 8-bit single-chip computer.

Every sensor of this model is temperature compensated and calibrated in accurate calibration chamber and the calibration-coefficient is saved in type of programme in OTP memory, when the sensor is detecting, it will cite coefficient from memory.

Small size & low consumption & long transmission distance(20m) enable DHT22 to be suited in all kinds of harsh application occasions.

Single-row packaged with four pins, making the connection very convenient.

3. Technical Specification:

Model	DHT22
Power supply	3.3-6V DC
Output signal	digital signal via single-bus
Sensing element	Polymer capacitor
Operating range	humidity 0-100%RH; temperature -40~80Celsius
Accuracy	humidity +-2%RH(Max +-5%RH); temperature <+-0.5Celsius
Resolution or sensitivity	humidity 0.1%RH; temperature 0.1Celsius
Repeatability	humidity +-1%RH; temperature +-0.2Celsius
Humidity hysteresis	+-0.3%RH
Long-term Stability	+-0.5%RH/year
Sensing period	Average: 2s
Interchangeability	fully interchangeable
Dimensions	small size 14*18*5.5mm; big size 22*28*5mm

4. Dimensions: (unit----mm)

1) Small size dimensions: (unit----mm)

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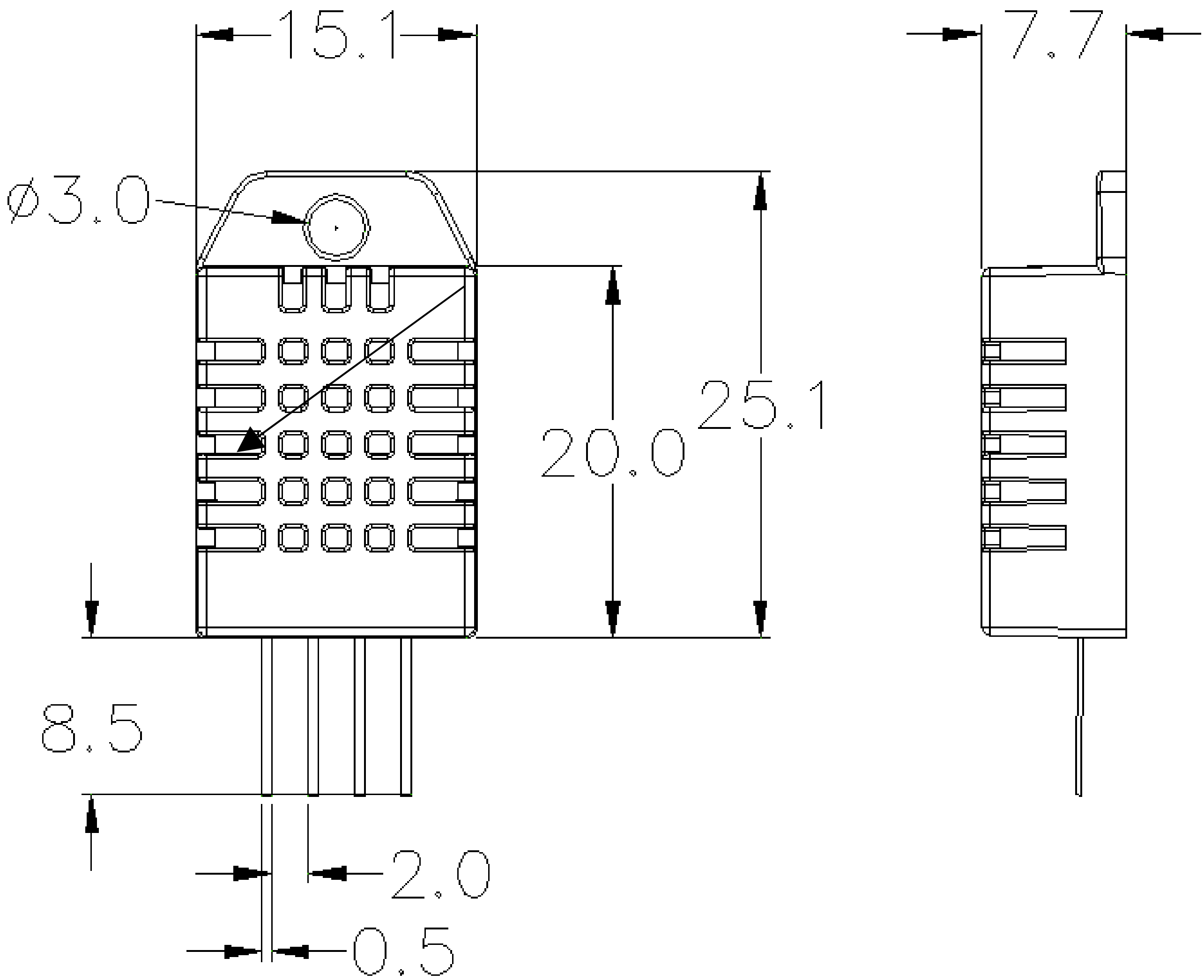

Pin sequence number: 1 2 3 4 (from left to right direction).

Pin	Function
1	VDD----power supply
2	DATA--signal
3	NULL
4	GND

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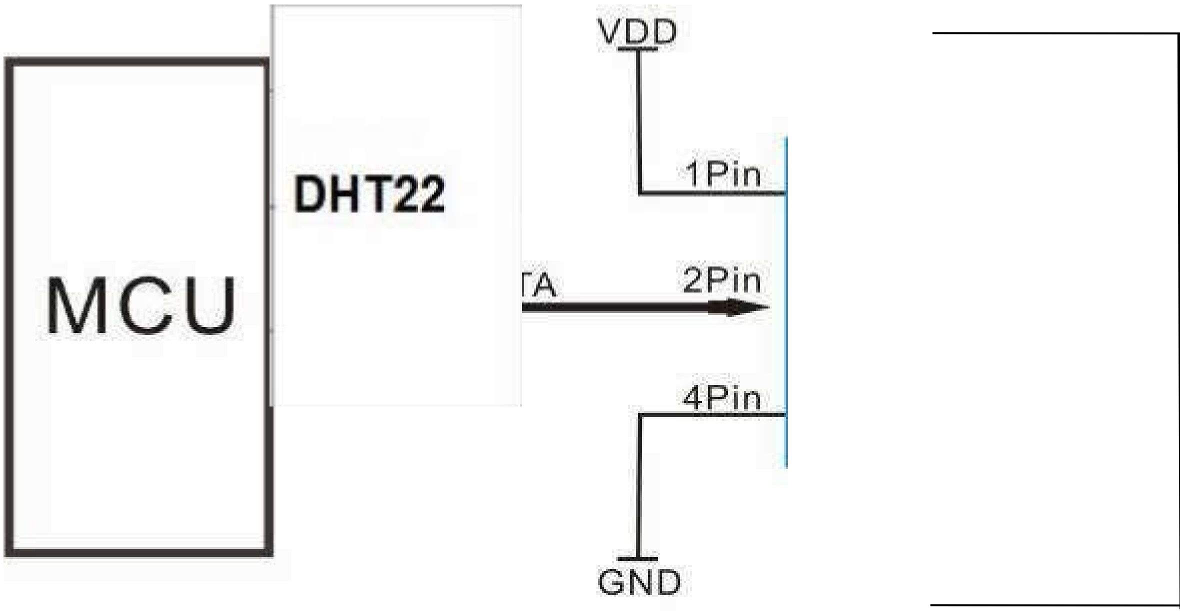
5. Electrical connection diagram:



3Pin---NC, AM2302 is another name for DHT22

6. Operating specifications:

(1) Power and Pins

Power's voltage should be 3.3-6V DC. When power is supplied to sensor, don't send any instruction to the sensor within one second to pass unstable status. One capacitor valued 100nF can be added between VDD and GND for wave filtering.

(2) Communication and signal

Single-bus data is used for communication between MCU and DHT22, it costs 5mS for single time communication.

Data is comprised of integral and decimal part, the following is the formula for data.

DHT22 send out higher data bit firstly!

DATA=8 bit integral RH data+8 bit decimal RH data+8 bit integral T data+8 bit decimal T data+8 bit check-sum

If the data transmission is right, check-sum should be the last 8 bit of "8 bit integral RH data+8 bit decimal RH data+8 bit integral T data+8 bit decimal T data".

When MCU send start signal, DHT22 change from low-power-consumption-mode to running-mode. When MCU finishs sending the start signal, DHT22 will send response signal of 40-bit data that reflect the relative humidity

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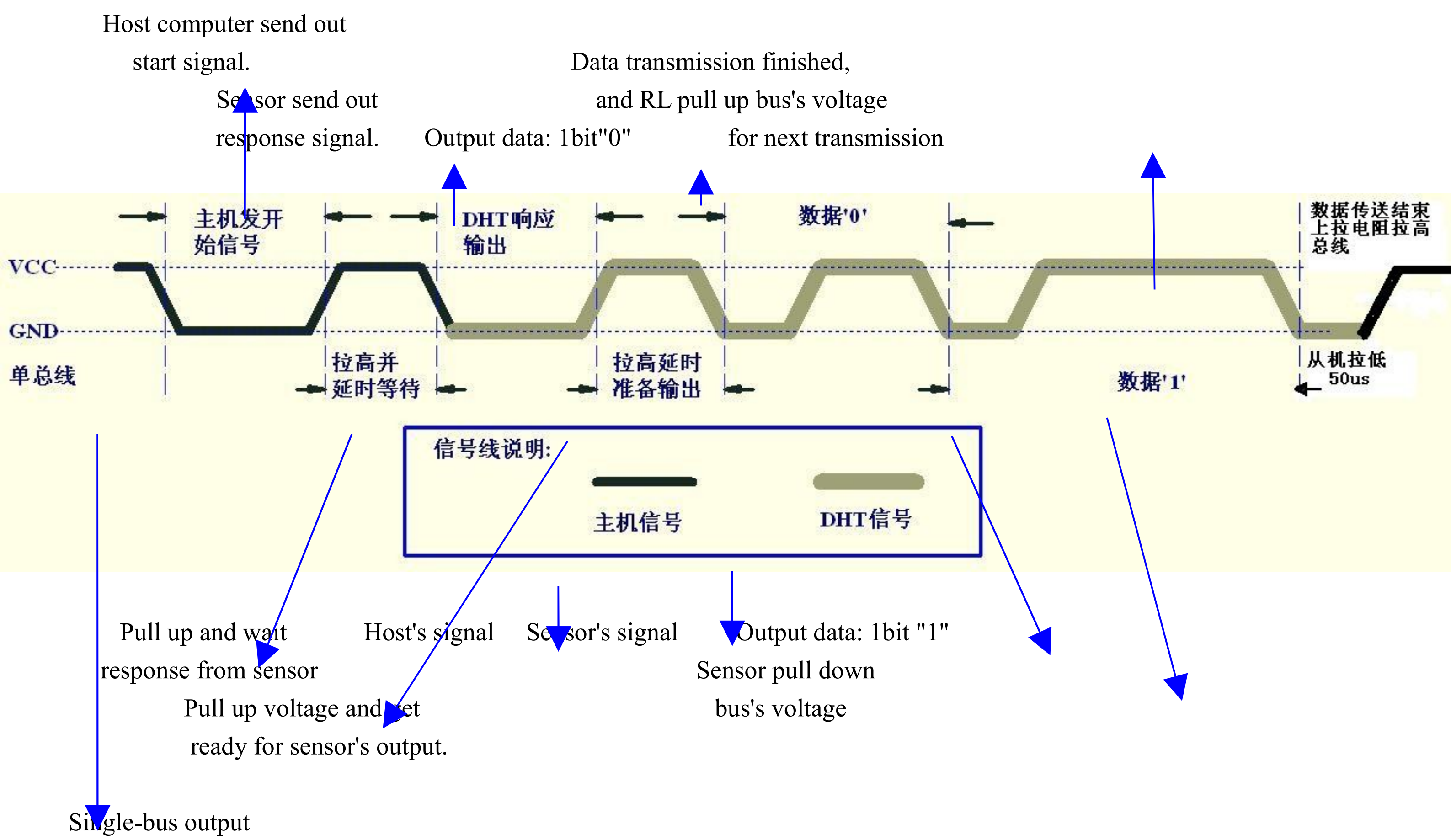
and temperature information to MCU. Without start signal from MCU, DHT22 will not give response signal to MCU. One start signal for one time's response data that reflect the relative humidity and temperature information from DHT22. DHT22 will change to low-power-consumption-mode when data collecting finish if it don't receive start signal from MCU again.

1) Check bellow picture for overall communication process:



2) Step 1: MCU send out start signal to DHT22

Data-bus's free status is high voltage level. When communication between MCU and DHT22 begin, program of MCU will transform data-bus's voltage level from high to low level and this process must beyond at least 1ms to ensure DHT22 could detect MCU's signal, then MCU will wait 20-40us for DHT22's response.

Check bellow picture for step 1:

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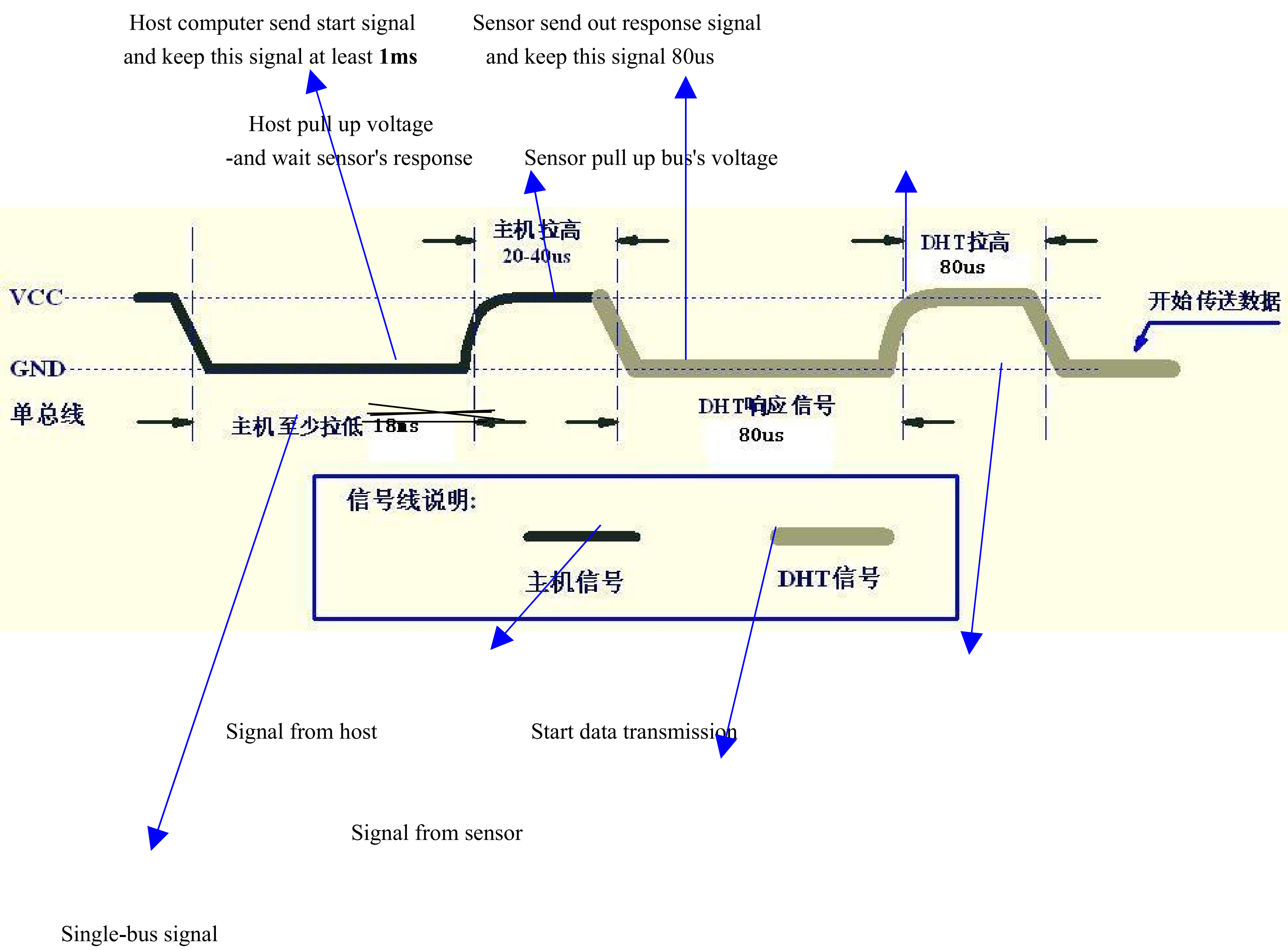

Step 2: DHT22 send response signal to MCU

When DHT22 detect the start signal, DHT22 will send out low-voltage-level signal and this signal last 80us as response signal, then program of DHT22 transform data-bus's voltage level from low to high level and last 80us for DHT22's preparation to send data.

Check bellow picture for step 2:

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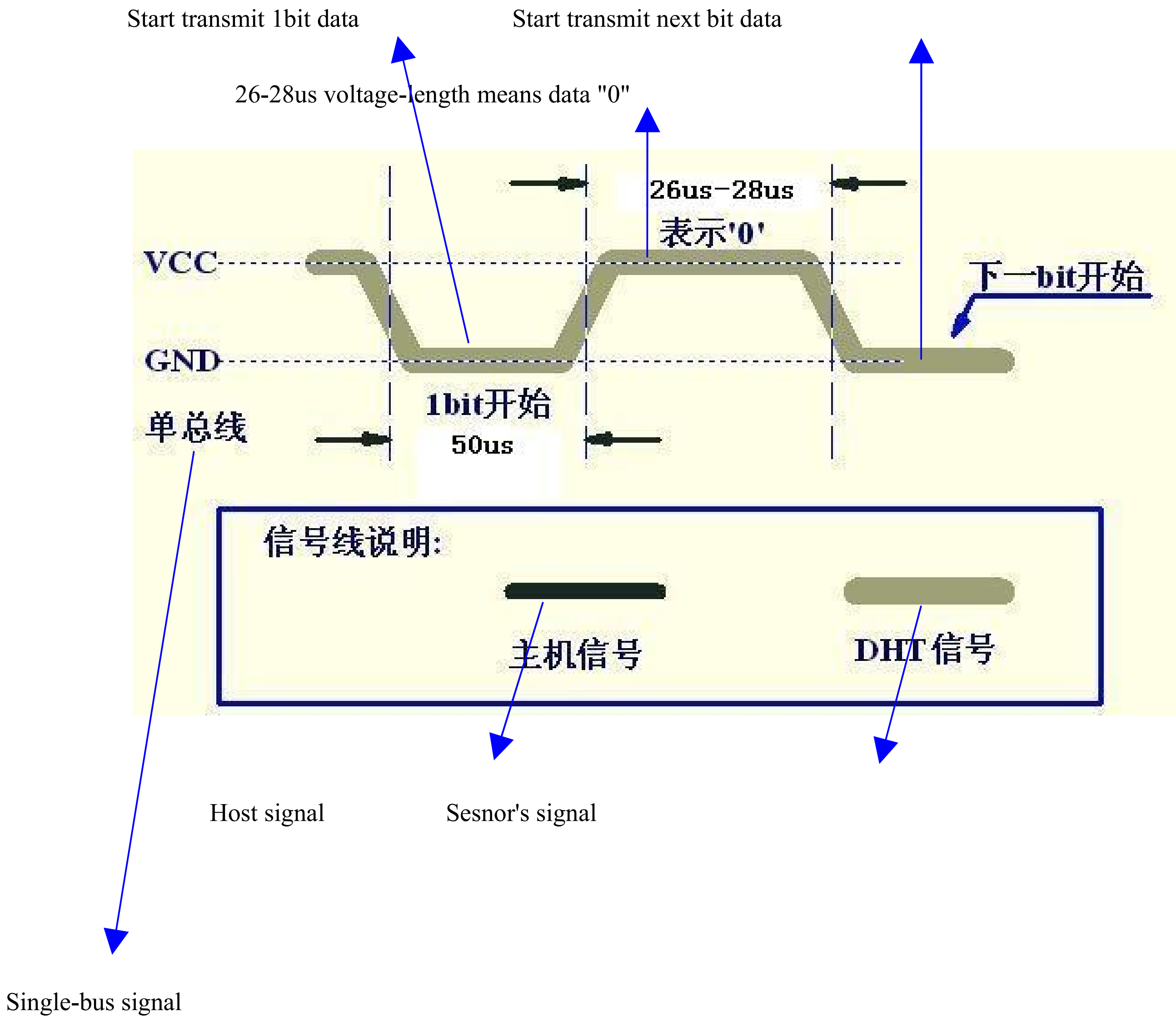

Step 3: DHT22 send data to MCU

When DHT22 is sending data to MCU, every bit's transmission begin with low-voltage-level that last 50us, the following high-voltage-level signal's length decide the bit is "1" or "0".

Check bellow picture for step 3:

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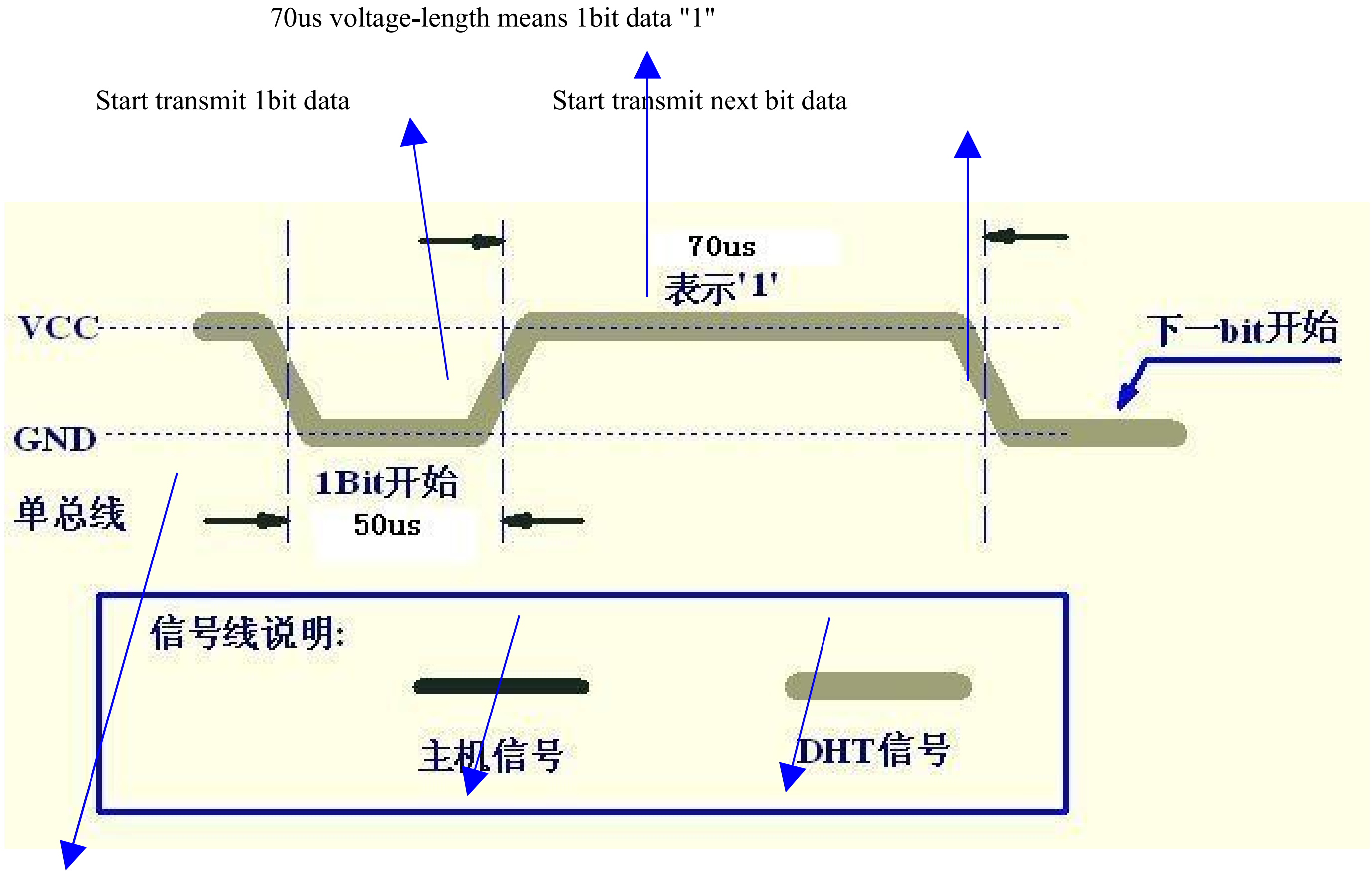

Host signal   Sesnor's signal

Single-bus signal

If signal from DHT22 is always high-voltage-level, it means DHT22 is not working properly, please check the electrical connection status.

7. Electrical Characteristics:

Item	Condition	Min	Typical	Max	Unit
Power supply	DC	3.3	5	6	V
Current supply	Measuring	1		1.5	mA
	Stand-by	40	Null	50	uA
Collecting period	Second		2		Second

*Collecting period should be : >2 second.

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8. Attentions of application:

(1) Operating and storage conditions

We don't recommend the applying RH-range beyond the range stated in this specification. The DHT22 sensor can recover after working in non-normal operating condition to calibrated status, but will accelerate sensors' aging.

(2) Attentions to chemical materials

Vapor from chemical materials may interfere DHT22's sensitive-elements and debase DHT22's sensitivity.

(3) Disposal when (1) & (2) happens

Step one: Keep the DHT22 sensor at condition of Temperature 50~60Celsius, humidity <10%RH for 2 hours;

Step two: After step one, keep the DHT22 sensor at condition of Temperature 20~30Celsius, humidity >70%RH for 5 hours.

(4) Attention to temperature's affection

Relative humidity strongly depend on temperature, that is why we use temperature compensation technology to ensure accurate measurement of RH. But it's still be much better to keep the sensor at same temperature when sensing.

DHT22 should be mounted at the place as far as possible from parts that may cause change to temperature.

(5) Attentions to light

Long time exposure to strong light and ultraviolet may debase DHT22's performance.

(6) Attentions to connection wires

The connection wires' quality will effect communication's quality and distance, high quality shielding-wire is recommended.

(7) Other attentions

* Welding temperature should be bellow 260Celsius.
* Avoid using the sensor under dew condition.
* Don't use this product in safety or emergency stop devices or any other occasion that failure of DHT22 may cause personal injury.

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Data sheet

BMP180
Digital pressure sensor

Bosch Sensortec

BMP180 Data sheet

Document revision	2.5
Document release date	5 April 2013
Document number	BST-BMP180-DS000-09
Technical reference code(s)	0 273 300 244
Notes	Data in this document are subject to change without notice. Product photos and pictures are for illustration purposes only and may differ from the real product's appearance.

BMP180

DIGITAL PRESSURE SENSOR

Key features

Pressure range:	300 ... 1100hPa (+9000m ... -500m relating to sea level)
Supply voltage:	1.8 ... 3.6V (V_{DD}) 1.62V ... 3.6V (V_{DDIO})
Package:	LGA package with metal lid Small footprint: 3.6mm x 3.8mm Super-flat: 0.93mm height
Low power:	5μA at 1 sample / sec. in standard mode
Low noise:	0.06hPa (0.5m) in ultra low power mode 0.02hPa (0.17m) advanced resolution mode

- Temperature measurement included
- I^2C interface
- Fully calibrated
- Pb-free, halogen-free and RoHS compliant,
- MSL 1

Typical applications

- Enhancement of GPS navigation (dead-reckoning, slope detection, etc.)
- In- and out-door navigation
- Leisure and sports
- Weather forecast
- Vertical velocity indication (rise/sink speed)

BMP180 general description

The BMP180 is the function compatible successor of the BMP085, a new generation of high precision digital pressure sensors for consumer applications.

The ultra-low power, low voltage electronics of the BMP180 is optimized for use in mobile phones, PDAs, GPS navigation devices and outdoor equipment. With a low altitude noise of merely 0.25m at fast conversion time, the BMP180 offers superior performance. The I^2C interface allows for easy system integration with a microcontroller.

The BMP180 is based on piezo-resistive technology for EMC robustness, high accuracy and linearity as well as long term stability.

Robert Bosch is the world market leader for pressure sensors in automotive applications. Based on the experience of over 400 million pressure sensors in the field, the BMP180 continues a new generation of micro-machined pressure sensors.

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1. Electrical characteristics

If not stated otherwise, the given values are ±3-Sigma values over temperature/voltage range in the given operation mode. All values represent the new parts specification; additional solder drift is shown separately.

Table 1: Operating conditions, output signal and mechanical characteristics

Parameter	Symbol	Condition	Min	Typ	Max	Units
Operating temperature	T_A	operational	-40		+85	°C
		full accuracy	0		+65	
Supply voltage	V_{DD}	ripple max. 50mVpp	1.8	2.5	3.6	V
			1.62	2.5	3.6	
Supply current @ 1 sample / sec. 25°C	I_{DDLOW}	ultra low power mode		3		µA
	I_{DDSTD}	standard mode		5		µA
	I_{DDHR}	high resolution mode		7		µA
	I_{DDUHR}	Ultra high res. mode		12		µA
	I_{DDAR}	Advanced res. mode		32		µA
Peak current	I_{peak}	during conversion		650	1000	µA
Standby current	I_{DDSBM}	@ 25°C		0.1	4[1]	µA
Relative accuracy pressure V_{DD} = 3.3V		950 . . . 1050 hPa @ 25 °C		±0.12		hPa
				±1.0		m
		700 ... 900hPa 25 . . . 40 °C		±0.12		hPa
				±1.0		m
Absolute accuracy pressure V_{DD} = 3.3V		300 . . . 1100 hPa 0 . . . +65 °C	-4.0	-1.0*	+2.0	hPa
		300 . . . 1100 hPa -20 . . . 0 °C	-6.0	-1.0*	+4.5	hPa
Resolution of output data		pressure		0.01		hPa
		temperature		0.1		°C
Noise in pressure		see table on page 12-13				
Absolute accuracy temperature V_{DD} = 3.3V		@ 25 °C	-1.5	±0.5	+1.5	°C
		0 . . . +65 °C	-2.0	±1.0	+2.0	°C

[1] at 85°C

Conversion time pressure	$t_{c\_p\_low}$	ultra low power mode		3	4.5	ms
	$t_{c\_p\_std}$	standard mode		5	7.5	ms
	$t_{c\_p\_hr}$	high resolution mode		9	13.5	ms
	$t_{c\_p\_luhr}$	ultra high res. mode		17	25.5	ms
	$t_{c\_p\_ar}$	Advanced res. mode		51	76.5	ms
Conversion time temperature	t_{C_temp}	standard mode		3	4.5	ms
Serial data clock	f_{SCL}				3.4	MHz
Solder drifts		Minimum solder height 50µm	-0.5		+2	hPa
Long term stability**		12 months		±1.0		hPa

* The typical value is: -1±1
** Long term stability is specified in the full accuracy operating pressure range 0 ... 65°C

2. Absolute maximum ratings

Table 2: Absolute maximum ratings

Parameter	Condition	Min	Max	Units
Storage temperature		-40	+85	°C
Supply voltage	all pins	-0.3	+4.25	V
ESD rating	HBM, R = 1.5kΩ, C = 100pF		±2	kV
Overpressure			10,000	hPa

The BMP180 has to be handled as Electrostatic Sensitive Device (ESD).

Figure 1: ESD

3. Operation

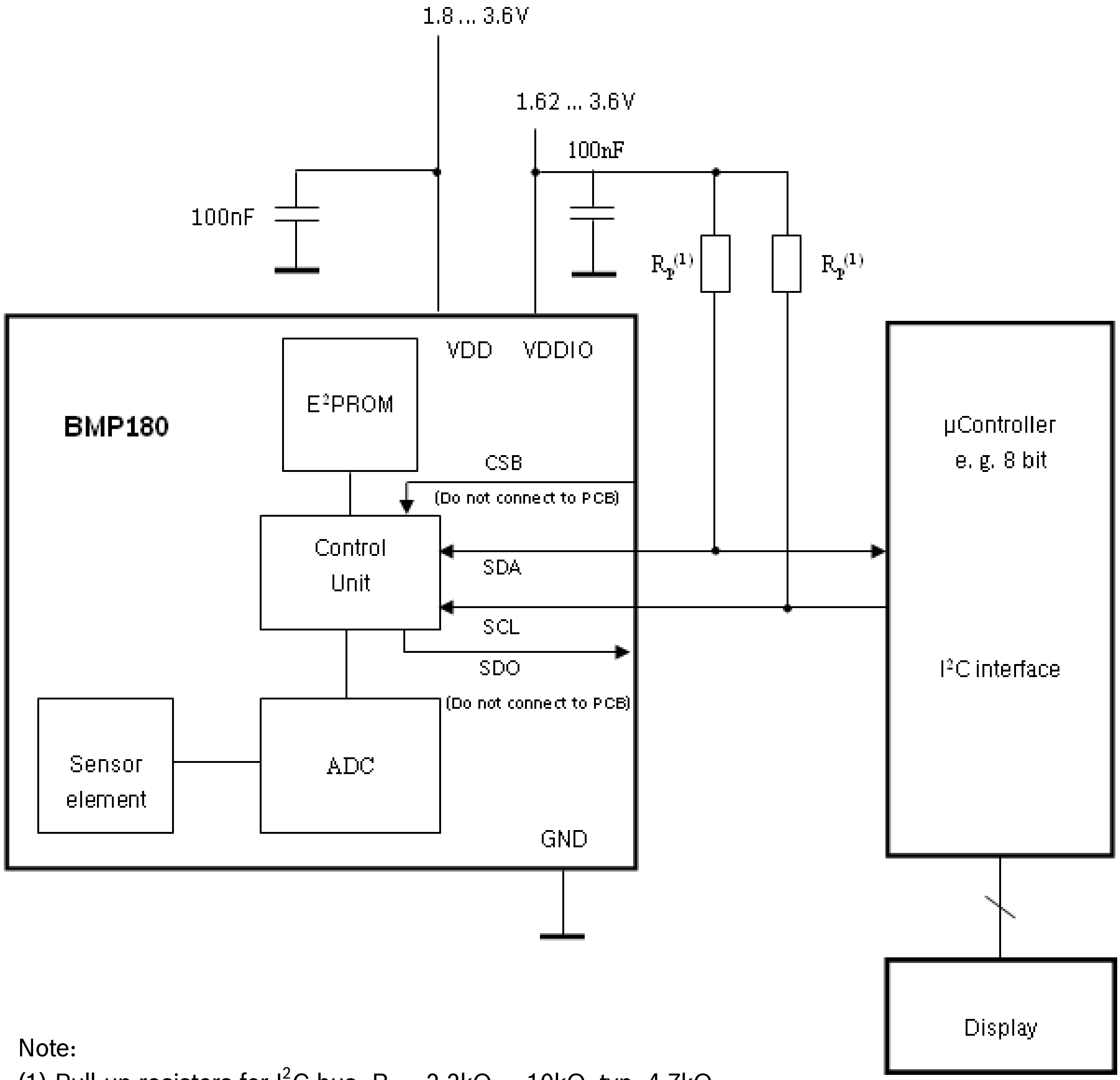
3.1 General description

The BMP180 is designed to be connected directly to a microcontroller of a mobile device via the I^2C bus. The pressure and temperature data has to be compensated by the calibration data of the E^2PROM of the BMP180.

3.2 General function and application schematics

The BMP180 consists of a piezo-resistive sensor, an analog to digital converter and a control unit with E^2PROM and a serial I^2C interface. The BMP180 delivers the uncompensated value of pressure and temperature. The E^2PROM has stored 176 bit of individual calibration data. This is used to compensate offset, temperature dependence and other parameters of the sensor.

- UP = pressure data (16 to 19 bit)
- UT = temperature data (16 bit)



Note:
(1) Pull-up resistors for I²C bus, R_p = 2.2kΩ ... 10kΩ, typ. 4.7kΩ

Figure 2: Typical application circuit

3.3 Measurement of pressure and temperature

For all calculations presented here an ANSI C code is available from Bosch Sensortec ("BMP180 _API").

The microcontroller sends a start sequence to start a pressure or temperature measurement. After converting time, the result value (UP or UT, respectively) can be read via the I^2C interface. For calculating temperature in °C and pressure in hPa, the calibration data has to be used. These constants can be read out from the BMP180 E^2PROM via the I^2C interface at software initialization.

The sampling rate can be increased up to 128 samples per second (standard mode) for dynamic measurement. In this case, it is sufficient to measure the temperature only once per second and to use this value for all pressure measurements during the same period.

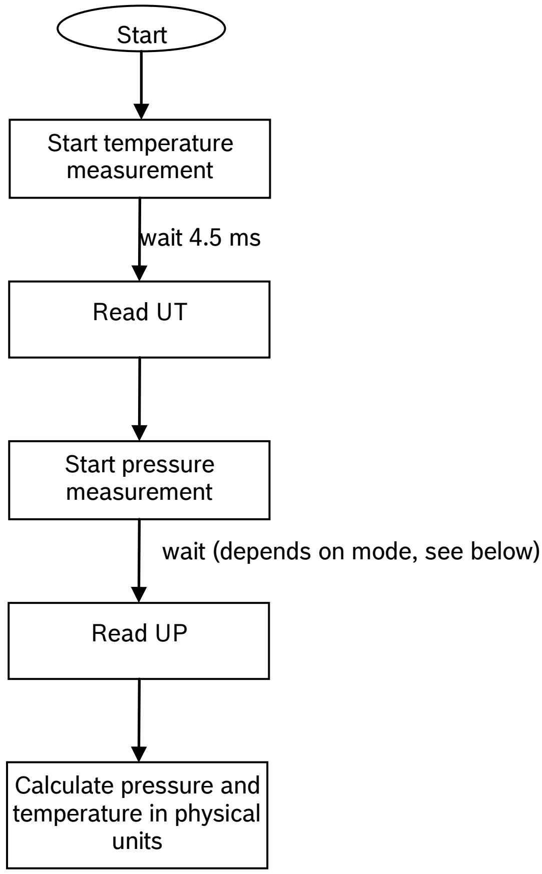


Figure 3: Measurement flow BMP180

3.3.1 Hardware pressure sampling accuracy modes

By using different modes the optimum compromise between power consumption, speed and resolution can be selected, see below table.

Table 3: Overview of BMP180 hardware accuracy modes, selected by driver software via the variable *oversampling_setting*

Mode	**Parameter** *oversampling_setting*	**Internal number of samples**	**Conversion time pressure max. [ms]**	**Avg. current @ 1 sample/s typ. [μA]**	**RMS noise typ. [hPa]**	**RMS noise typ. [m]**
ultra low power	0	1	4.5	3	0.06	0.5
standard	1	2	7.5	5	0.05	0.4
high resolution	2	4	13.5	7	0.04	0.3
ultra high resolution	3	8	25.5	12	0.03	0.25

For further information on noise characteristics see the relevant application note "Noise in pressure sensor applications".

All modes can be performed at higher speeds, e.g. up to 128 times per second for standard mode, with the current consumption increasing proportionally to the sample rate.

3.3.2 Software pressure sampling accuracy modes

For applications where a low noise level is critical, averaging is recommended if the lower bandwidth is acceptable. Oversampling can be enabled using the software API driver (with OSR = 3).

Table 4: Overview of BMP180 software accuracy mode, selected by driver software via the variable *software_oversampling_setting*

Mode	Parameter *oversampling_setting*	software_ oversampling_setting	Conversion time pressure max. [ms]	Avg. current @ 1 sample/s typ. [µA]	RMS noise typ. [hPa]	RMS noise typ. [m]
Advanced resolution	3	1	76.5	32	0.02	0.17

3.4 Calibration coefficients

The 176 bit E^2PROM is partitioned in 11 words of 16 bit each. These contain 11 calibration coefficients. Every sensor module has individual coefficients. Before the first calculation of temperature and pressure, the master reads out the E^2PROM data.
The data communication can be checked by checking that none of the words has the value 0 or 0xFFFF.

Table 5: Calibration coefficients

	BMP180 reg adr	
Parameter	MSB	LSB
AC1	0xAA	0xAB
AC2	0xAC	0xAD
AC3	0xAE	0xAF
AC4	0xB0	0xB1
AC5	0xB2	0xB3
AC6	0xB4	0xB5
B1	0xB6	0xB7
B2	0xB8	0xB9
MB	0xBA	0xBB
MC	0xBC	0xBD
MD	0xBE	0xBF

3.5 Calculating pressure and temperature

The mode (ultra low power, standard, high, ultra high resolution) can be selected by the variable *oversampling_setting* (0, 1, 2, 3) in the C code.

Calculation of true temperature and pressure in steps of 1Pa (= 0.01hPa = 0.01mbar) and temperature in steps of 0.1°C.

The following figure shows the detailed algorithm for pressure and temperature measurement.

This algorithm is available to customers as reference C source code ("BMP180_ API") from Bosch Sensortec and via its sales and distribution partners. **Please contact your Bosch Sensortec representative for details.**

Calculation of pressure and temperature for BMP180

Start

Flowchart	example:		C code function:	type:
Read calibration data from the E^2PROM of the BMP180			bmp180_get_cal_param	
read out E^2PROM registers, 16 bit, MSB first				
AC1 (0xAA, 0xAB) (16 bit)	AC1 =	408		short
AC2 (0xAC, 0xAD) (16 bit)	AC2 =	-72		short
AC3 (0xAE, 0xAF) (16 bit)	AC3 =	-14383		short
AC4 (0xB0, 0xB1) (16 bit)	AC4 =	32741		unsigned short
AC5 (0xB2, 0xB3) (16 bit)	AC5 =	32757		unsigned short
AC6 (0xB4, 0xB5) (16 bit)	AC6 =	23153		unsigned short
B1 (0xB6, 0xB7) (16 bit)	B1 =	6190		short
B2 (0xB8, 0xB9) (16 bit)	B2 =	4		short
MB (0xBa, 0xBB) (16 bit)	MB =	-32768		short
MC (0xBC, 0xBD) (16 bit)	MC =	-8711		short
MD (0xBE, 0xBF) (16 bit)	MD =	2868		short
read uncompensated temperature value			bmp180_get_ut	
write 0x2E into reg 0xF4, wait 4.5ms				
read reg 0xF6 (MSB), 0xF7 (LSB)				
UT = MSB << 8 + LSB	UT =	**27898**		long
	oss =	0		
	= oversampling_setting			short (0 .. 3)
	(ultra low power mode)		bmp180_get_up	
read uncompensated pressure value				
write 0x34+(oss<<6) into reg 0xF4, wait				
read reg 0xF6 (MSB), 0xF7 (LSB), 0xF8 (XLSB)				
UP = (MSB<<16 + LSB<<8 + XLSB) >> (8-oss)	UP =	**23843**		long
calculate true temperature			bmp180_get_temperature	
$X1 = (UT - AC6) * AC5 / 2^{15}$	X1 =	4743		long
$X2 = MC * 2^{11} / (X1 + MD)$	X2 =	-2344		long
$B5 = X1 + X2$	B5 =	2399		long
$T = (B5 + 8) / 2^4$	**T =**	**150**	***temp in 0.1°C***	long
calculate true pressure			BMP180_calpressure	
$B6 = B5 - 4000$	B6 =	-1601		long
$X1 = (B2 * (B6 * B6 / 2^{12})) / 2^{11}$	X1 =	1		long
$X2 = AC2 * B6 / 2^{11}$	X2 =	56		long
$X3 = X1 + X2$	X3 =	57		long
B3 = (((AC1*4+X3) << oss) + 2) / 4	B3 =	422		long
$X1 = AC3 * B6 / 2^{13}$	X1 =	2810		long
$X2 = (B1 * (B6 * B6 / 2^{12})) / 2^{16}$	X2 =	59		long
$X3 = ((X1 + X2) + 2) / 2^2$	X3 =	717		long
$B4 = AC4 * (unsigend long)(X3 + 32768) / 2^{15}$	B4 =	33457		unsigned long
B7 = ((unsigned long)UP - B3) * (50000 >> oss)	B7 =	1171050000		unsigned long
if (B7 < 0x80000000) { p = (B7 * 2) / B4 }	p =	70003		long
else { p = (B7 / B4) * 2 }				long
$X1 = (p / 2^8) * (p / 2^8)$	X1 =	74529		long
$X1 = (X1 * 3038) / 2^{16}$	X1 =	3454		long
$X2 = (-7357 * p) / 2^{16}$	X2 =	-7859		long
$p = p + (X1 + X2 + 3791) / 2^4$	**p =**	**69964**	***press. in Pa***	long
display temperature and pressure value				

Figure 4: Algorithm for pressure and temperature measurement

3.6 Calculating absolute altitude

With the measured pressure *p* and the pressure at sea level p_0 e.g. 1013.25hPa, the altitude in meters can be calculated with the international barometric formula:

$$altitude = 44330 * \left(1 - \left(\frac{p}{p_0}\right)^{\frac{1}{5.255}}\right)$$

Thus, a pressure change of Δp = 1hPa corresponds to 8.43m at sea level.

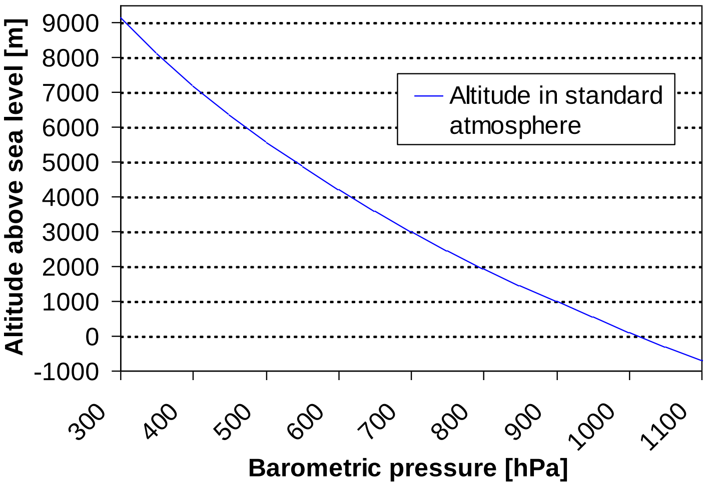


Figure 5: Transfer function: Altitude over sea level – Barometric pressure

3.7 Calculating pressure at sea level

With the measured pressure *p* and the absolute altitude the pressure at sea level can be calculated:

$$p_0 = \frac{p}{\left(1 - \frac{\text{altitude}}{44330}\right)^{5.255}}$$

Thus, a difference in altitude of Δaltitude = 10m corresponds to 1.2hPa pressure change at sea level.

4. Global Memory Map

The memory map below shows all externally accessible data registers which are needed to operate BMP180. The left columns show the memory addresses. The columns in the middle depict the content of each register bit. The colors of the bits indicate whether they are read-only, write-only or read- and writable. The memory is volatile so that the writable content has to be re-written after each power-on.
Not all register addresses are shown. These registers are reserved for further Bosch factory testing and trimming.

Register Name	Register Adress	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0	Reset state
out_xlsb	F8h	adc_out_xlsb<7:3>					0	0	0	00h
out_lsb	F7h	adc_out_lsb<7:0>								00h
out_msb	F6h	adc_out_msb<7:0>								80h
ctrl_meas	F4h	oss<1:0>		sco	measurement control					00h
soft reset	E0h	reset								00h
id	D0h	id<7:0>								55h
calib21 downto calib0	BFh *down* to AAh	calib21<7:0> *down* to calib0<7:0>								n/a

Registers:	Control registers	Calibration registers	Data registers	Fixed
Type:	read / write	read only	read only	read only

Figure 6: Memory map

Measurement control (register F4h <4:0>): Controls measurements. Refer to Figure 6 for usage details.

Sco (register F4h <5>): Start of conversion. The value of this bit stays “1” during conversion and is reset to “0” after conversion is complete (data registers are filled).

Oss (register F4h <7:6>): controls the oversampling ratio of the pressure measurement (00b: single, 01b: 2 times, 10b: 4 times, 11b: 8 times).

Soft reset (register E0h): Write only register. If set to 0xB6, will perform the same sequence as power on reset.

Chip-id (register D0h): This value is fixed to 0x55 and can be used to check whether communication is functioning.

After conversion, data registers can be read out in any sequence (i.e. MSB first or LSB first). Using a burst read is not mandatory.

5. I^2C Interface

- I^2C is a digital two wire interface
- Clock frequencies up to 3.4Mbit/sec. (I^2C standard, fast and high-speed mode supported)
- SCL and SDA needs a pull-up resistor, typ. 4.7kOhm to V_{DDIO}
  (one resistor each for all the I^2C bus)

The I^2C bus is used to control the sensor, to read calibration data from the E^2PROM and to read the measurement data when A/D conversion is finished. SDA (serial data) and SCL (serial clock) have open-drain outputs.

For detailed I^2C-bus specification please refer to:
http://www.nxp.com/acrobat_download/literature/9398/39340011.pdf

5.1 I^2C specification

Table 6: Electrical parameters for the I^2C interface

Parameter	Symbol	Min.	Typ	Max.	Units
Clock input frequency	f_{SCL}			3.4	MHz
Input-low level	V_{IL}	0		0.2 * V_{DDIO}	V
Input-high level	V_{IH}	0.8 * V_{DDIO}		V_{DDIO}	V
Voltage output low level @ V_{DDIO} = 1.62V, I_{OL} = 3mA	V_{OL}			0.3	V
SDA and SCL pull-up resistor	$R_{pull-up}$	2.2		10	kOhm
SDA sink current @ V_{DDIO} = 1.62V, V_{OL} = 0.3V	I_{SDA_sink}		9		mA
Start-up time after power-up, before first communication	t_{Start}	10			Ms

5.2 Device and register address

The BMP180 module address is shown below. The LSB of the device address distinguishes between read (1) and write (0) operation, corresponding to address 0xEF (read) and 0xEE (write).

Table 7: BMP180 addresses

A7	A6	A5	A4	A3	A2	A1	W/R
1	1	1	0	1	1	1	0/1

5.3 I²C protocol

The I²C interface protocol has special bus signal conditions. Start (S), stop (P) and binary data conditions are shown below. At start condition, SCL is high and SDA has a falling edge. Then the slave address is sent. After the 7 address bits, the direction control bit R/W selects the read or write operation. When a slave device recognizes that it is being addressed, it should acknowledge by pulling SDA low in the ninth SCL (ACK) cycle.
At stop condition, SCL is also high, but SDA has a rising edge. Data must be held stable at SDA when SCL is high. Data can change value at SDA only when SCL is low.
Even though V_{DDIO} can be powered on before V_{DD}, there is a chance of excessive power consumption (a few mA) if this sequence is used, and the state of the output pins is undefined so that the bus can be locked. Therefore, V_{DD} *must* be powered before V_{DDIO} unless the limitations above are understood and not critical.

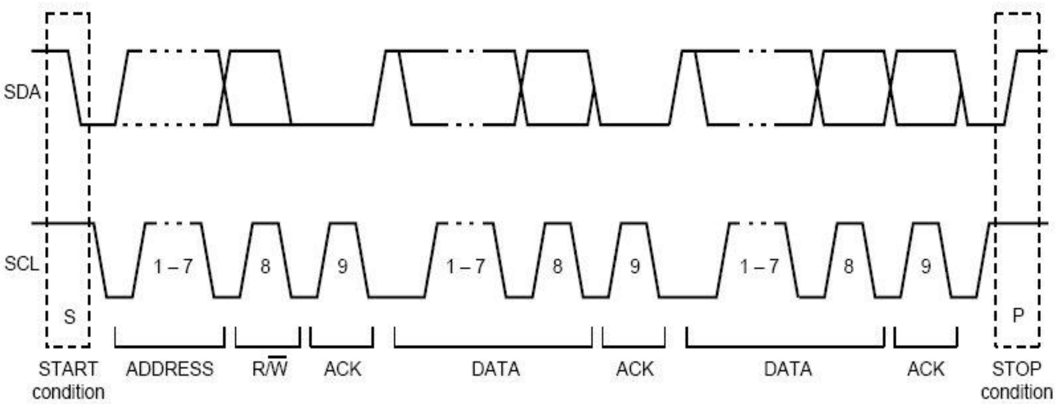


Figure 7: I²C protocol

5.4 Start temperature and pressure measurement

The timing diagrams to start the measurement of the temperature value UT and pressure value UP are shown below. After start condition the master sends the device address write, the register address and the control register data. The BMP180 sends an acknowledgement (ACKS) every 8 data bits when data is received. The master sends a stop condition after the last ACKS.

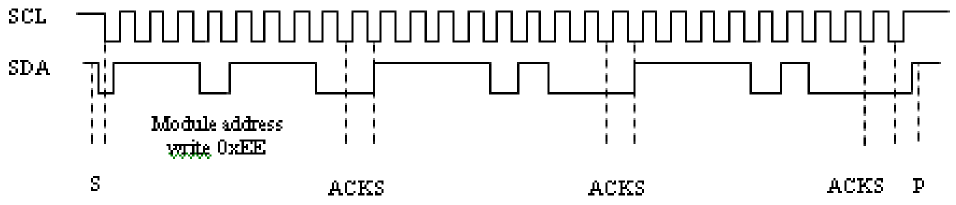


Figure 8: Timing diagram for starting pressure measurement

Abbreviations:

S	Start
P	Stop
ACKS	Acknowledge by Slave
ACKM	Acknowledge by Master
NACKM	Not Acknowledge by Master

Table 8: Control registers values for different internal oversampling_setting (oss)

Measurement	Control register value (register address 0xF4)	Max. conversion time [ms]
Temperature	0x2E	4.5
Pressure (oss = 0)	0x34	4.5
Pressure (oss = 1)	0x74	7.5
Pressure (oss = 2)	0xB4	13.5
Pressure (oss = 3)	0xF4	25.5

5.5 Read A/D conversion result or E²PROM data

To read out the temperature data word UT (16 bit), the pressure data word UP (16 to 19 bit) and the E²PROM data proceed as follows:

After the start condition the master sends the module address write command and register address. The register address selects the read register:

E²PROM data registers 0xAA to 0xBF
Temperature or pressure value UT or UP 0xF6 (MSB), 0xF7 (LSB), optionally 0xF8 (XLSB)

Then the master sends a restart condition followed by the module address read that will be acknowledged by the BMP180 (ACKS). The BMP180 sends first the 8 MSB, acknowledged by the master (ACKM), then the 8 LSB. The master sends a "not acknowledge" (NACKM) and finally a stop condition.

Optionally for ultra high resolution, the XLSB register with address 0xF8 can be read to extend the 16 bit word to up to 19 bits; refer to the application programming interface (API) software rev. 1.1 ("BMP180_ API", available from Bosch Sensortec).

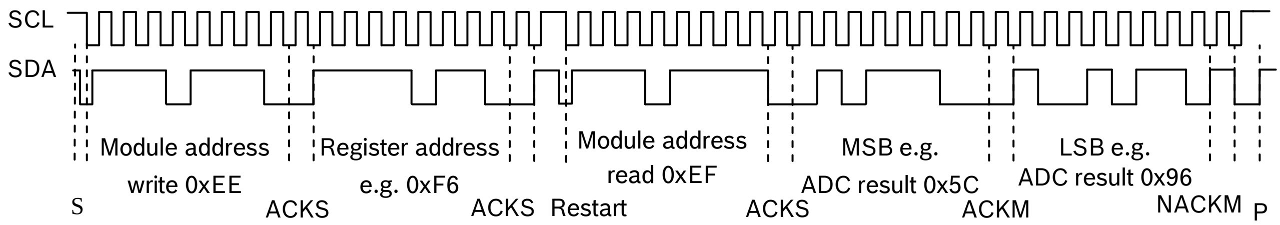


Figure 9: Timing diagram read 16 bit A/D conversion result

6. Package

6.1 Pin configuration

Picture shows the device in top view. Device pins are shown here transparently only for orientation purposes.

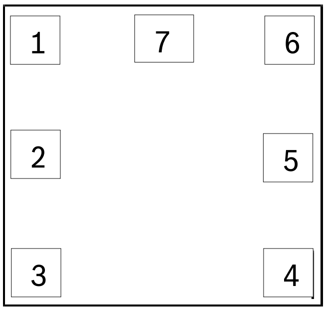


Figure 10: Layout pin configuration BMP180

Table 9: Pin configuration BMP180

in No	Name	Function
1	CSB*	Chip select
2	VDD	Power supply
3	VDDIO	Digital power supply
4	SDO*	SPI output
5	SCL	I2C serial bus clock input
6	SDA	I2C serial bus data (or SPI input)
7	GND	Ground

* A pin compatible product variant with SPI interface is possible upon customer's request. For I^{2}C (standard case) CSB and SDO are not used, they have to be left open.
All pins have to be soldered to the PCB for symmetrical stress input even though they are not connected internally.

6.2 Outline dimensions

The sensor housing is a 7Pin LGA package with metal lid. Its dimensions are 3.60mm (±0.1 mm) x 3.80mm (±0.1 mm) x 0.93mm (±0.07 mm).

Note: All dimensions are in mm.

6.2.1 Bottom view

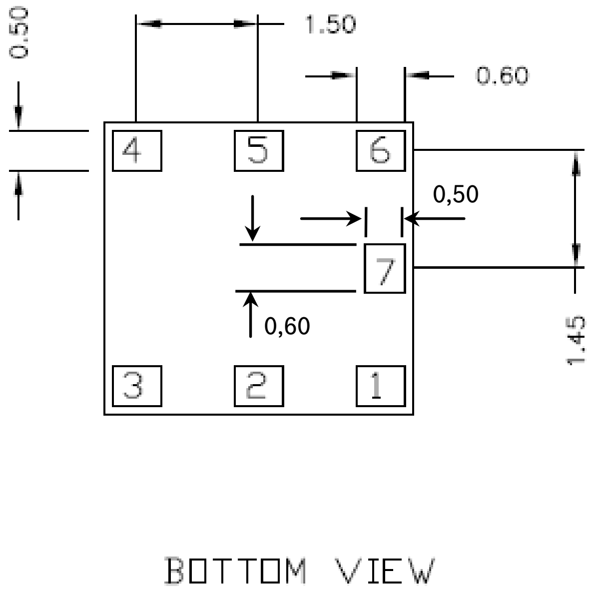


Figure 11: Bottom view BMP180

6.2.2 Top view

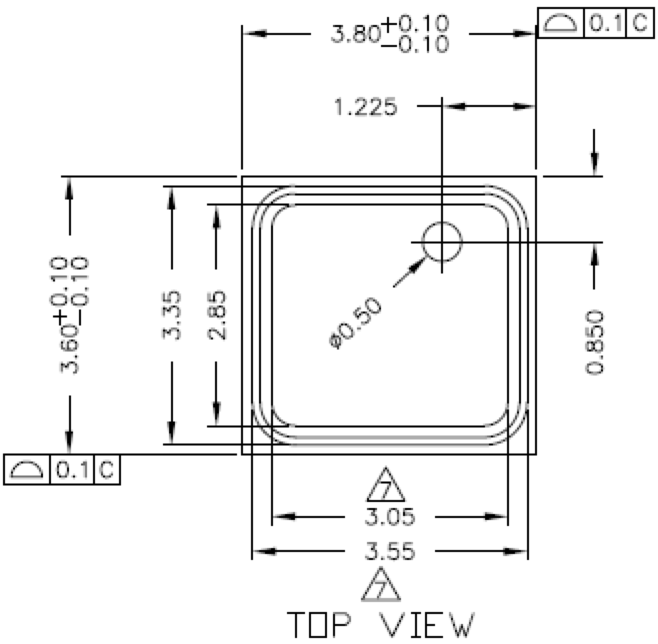


Figure 12: Top view BMP180

6.2.3 Side view

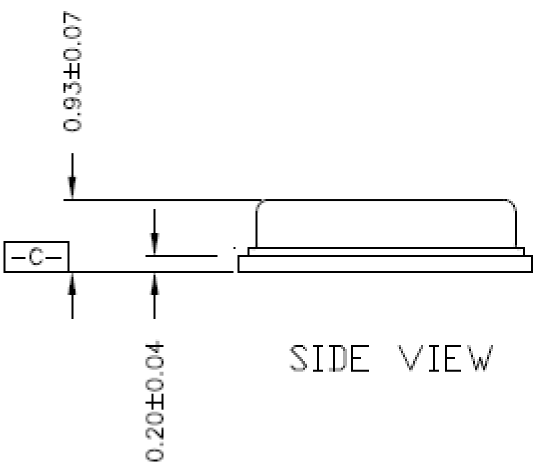


Figure 13: Side view BMP180

6.3 Moisture sensitivity level and soldering

The BMP180 is classified MSL 1 (moisture sensitivity level) according to IPC/JEDEC standards J-STD-020D and J-STD-033A.

The device can be soldered Pb-free with a peak temperature of 260°C for 20 to 40 sec. The minimum height of the solder after reflow shall be at least 50µm. This is required for good mechanical decoupling between the sensor device and the printed circuit board (PCB).

To ensure good solder-ability, the devices shall be stored at room temperature (20°C).

The soldering process can lead to an offset shift.

6.4 RoHS compliancy

The BMP180 sensor meets the requirements of the EC directive "Restriction of hazardous substances (RoHS)", please refer also to:

"Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronic equipment".

The BMP180 sensor is also halogen-free.

6.5 Mounting and assembly recommendations

In order to achieve the specified performance for you design, the following recommendations and the “Handling, soldering & mounting instructions BMP180” should be taken into consideration when mounting a pressure sensor on a printed-circuit board (PCB):

- The clearance above the metal lid shall be 0.1mm at minimum.
- For the device housing appropriate venting needs to be provided in case the ambient pressure shall be measured.
- Liquids shall not come into direct contact with the device.
- During operation the sensor is sensitive to light, which can influence the accuracy of the measurement (photo-current of silicon).
- The BMP180 shall not the placed close the fast heating parts. In case of gradients > 3°C/sec. it is recommended to follow Bosch Sensortec application note ANP015, "Correction of errors induced by fast temperature changes". Please contact your Bosch Sensortec representative for details.

7. Legal disclaimer

7.1 Engineering samples

Engineering Samples are marked with an asterisk (*) or (e). Samples may vary from the valid technical specifications of the product series contained in this data sheet. They are therefore not intended or fit for resale to third parties or for use in end products. Their sole purpose is internal client testing. The testing of an engineering sample may in no way replace the testing of a product series. Bosch Sensortec assumes no liability for the use of engineering samples. The Purchaser shall indemnify Bosch Sensortec from all claims arising from the use of engineering samples.

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Bosch Sensortec products are developed for the consumer goods industry. They may only be used within the parameters of this product data sheet. They are not fit for use in life-sustaining or security sensitive systems. Security sensitive systems are those for which a malfunction is expected to lead to bodily harm or significant property damage. In addition, they are not fit for use in products which interact with motor vehicle systems.

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The purchaser shall indemnify Bosch Sensortec from all third party claims arising from any product use not covered by the parameters of this product data sheet or not approved by Bosch Sensortec and reimburse Bosch Sensortec for all costs in connection with such claims.

The purchaser must monitor the market for the purchased products, particularly with regard to product safety, and inform Bosch Sensortec without delay of all security relevant incidents.

7.3 Application examples and hints

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8. Document history and modification

Rev. No	Chapter	Description of modifications/changes	Date
1.0		First edition for description of serial production material – Preliminary version	
1.1	5.1	New nomenclature of pin configuration	27 July 2010
1.2	5	Design change in package – hole in Lid and without slit	13 September 2010
1.3	3.2 5.1	- Standardizing pin naming over Bosch Sensortec products – typical application circuit - Optimizing pin description, SPI description	15 December 2010
2.0	1	- Non-preliminary version - Verifying parameter through characterization	28 January 2011
2.1	3.2 4 5.3 6.1 6.2.1	- Declaration of SDO and CSB pins in the typical application circuit - Adding global memory map and bits description - Power-up sequence - Description of used interfaces - Dimension pin7	1 April 2011
2.2	6.1	Correction of the pin configuration (editorial change)	14 April 2011
2.3	3.3	Optimizing noise performance	25 May 2011
2.4	6.3	Removed shelf-life constraints	26 January 2012
	page 2	Comparison removed	
	5.1	Voltage output low level added	
	5.3	Power on sequence of V_{DD} and V_{DDIO} defined	
2.5	1	Added max values for supply current for restricted version	15 Feb 2013
	1	Added max value for standby current for restricted version	5 Apr 2013
	Figure 4	Update of calculation of algorithm for pressure and temperature measurement	
	Page 2	Changed wording from “ultra high resolution mode” to “advanced resolution mode”	

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Revision_2.5_042013
Document number: BST-BMP180-DS000-09

TECHNICAL DATA MQ-135 GAS SENSOR

FEATURES

Wide detecting scope Fast response and High sensitivity
Stable and long life Simple drive circuit

APPLICATION

They are used in air quality control equipments for buildings/offices, are suitable for detecting of NH3,NOx, alcohol, Benzene, smoke,CO_2 ,etc.

SPECIFICATIONS

A. Standard work condition

Symbol	Parameter name	Technical condition	Remarks
Vc	Circuit voltage	5V±0.1	AC OR DC
V_H	Heating voltage	5V±0.1	ACOR DC
R_L	Load resistance	can adjust	
R_H	Heater resistance	33Ω ±5%	Room Tem
P_H	Heating consumption	less than 800mw	

B. Environment condition

Symbol	Parameter name	Technical condition	Remarks
Tao	Using Tem	-10℃…+45℃	
Tas	Storage Tem	-20℃…+70℃	
R_H	Related humidity	less than 95%Rh	
O_2	Oxygen concentration	21%(standard condition)Oxygen concentration can affect sensitivity	minimum value is over 2%

C. Sensitivity characteristic

Symbol	Parameter name	Technical parameter	Remark 2
Rs	Sensing Resistance	30KΩ -200KΩ (100ppm NH_3)	Detecting concentration scope： 10ppm-300ppm NH_3 10ppm-1000ppm Benzene 10ppm-300ppm Alcohol
α (200/50) NH_3	Concentration Slope rate	≤ 0.65	
Standard Detecting Condition	Temp: 20℃±2℃ Vc:5V±0.1 Humidity: 65%±5% Vh: 5V±0.1		
Preheat time	Over 24 hour		

D. Structure and configuration, basic measuring circuit

	Parts	Materials
1	Gas sensing layer	SnO_2
2	Electrode	Au
3	Electrode line	Pt
4	Heater coil	Ni-Cr alloy
5	Tubular ceramic	Al_2O_3
6	Anti-explosion network	Stainless steel gauze (SUS316 100-mesh)
7	Clamp ring	Copper plating Ni
8	Resin base	Bakelite
9	Tube Pin	Copper plating Ni

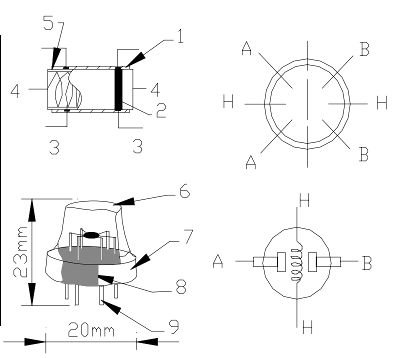


Fig. 1

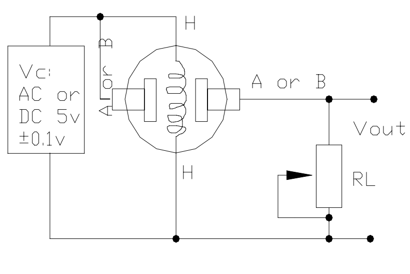
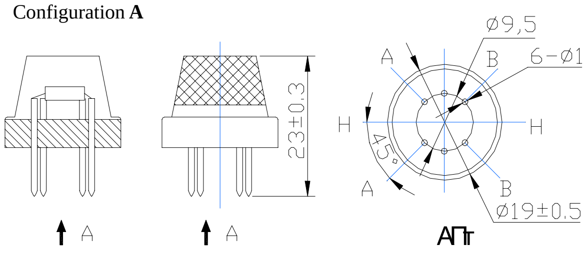
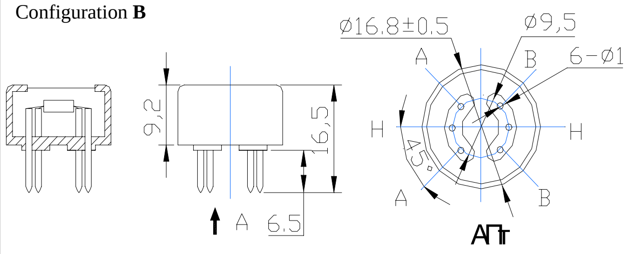


Fig.2

Configuration **A**



Configuration **B**



Structure and configuration of MQ-135 gas sensor is shown as Fig. 1 (Configuration **A or B**), sensor composed by micro AL_2O_3 ceramic tube, Tin Dioxide (SnO_2) sensitive layer, measuring electrode and heater are fixed into a crust made by plastic and stainless steel net. The heater provides necessary work conditions for work of sensitive components. The enveloped MQ-135 have 6 pins ,4 of them are used to fetch signals, and other 2 are used for providing heating current.

Electric parameter measurement circuit is shown as Fig.2

E. Sensitivity characteristic curve

Fig.2 sensitivity characteristics of the MQ-135

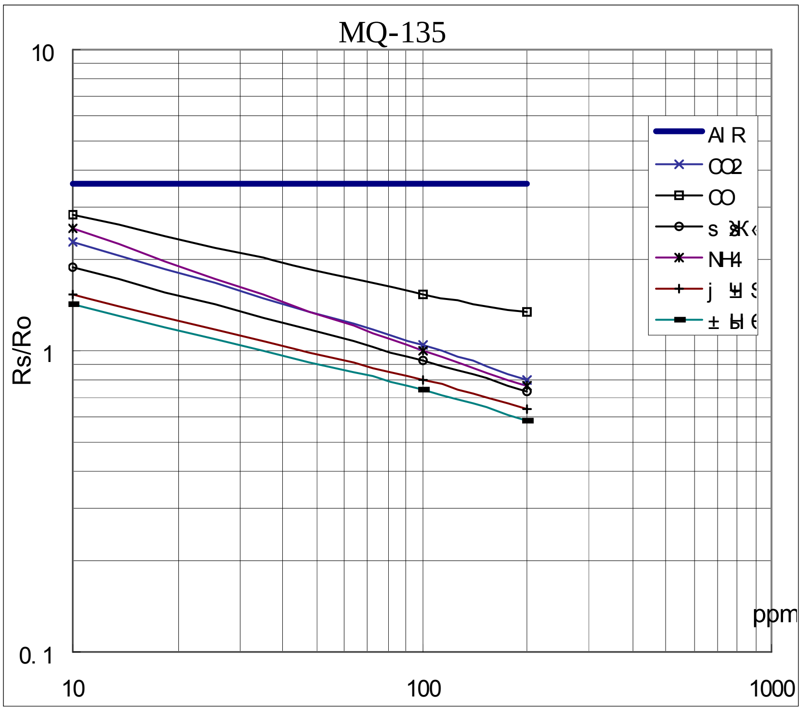


Fig.3 is shows the typical sensitivity characteristics of the MQ-135 for several gases.

in their: Temp: 20℃、 Humidity: 65%、 O_2 concentration 21% RL=20kΩ

Ro: sensor resistance at 100ppm of NH_3 in the clean air.

Rs: sensor resistance at various concentrations of gases.

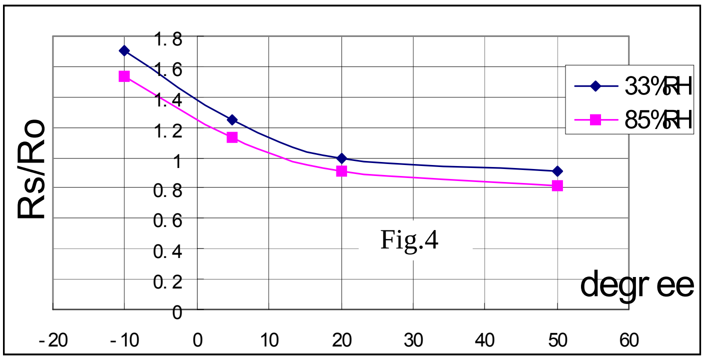


Fig.4

Fig.4 is shows the typical dependence of the MQ-135 on temperature and humidity.

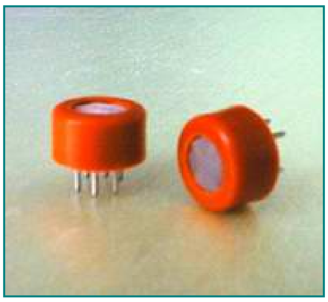
Ro: sensor resistance at 100ppm of NH_3 in air at 33%RH and 20 degree.

Rs: sensor resistance at 100ppm of NH_3 at different temperatures and humidities.

SENSITVITY ADJUSTMENT

Resistance value of MQ-135 is difference to various kinds and various concentration gases. So,When using this components, sensitivity adjustment is very necessary. we recommend that you calibrate the detector for 100ppm NH_3 or 50ppm Alcohol concentration in air and use value of Load resistancethat(R_L) about 20 KΩ (10KΩ to 47 KΩ).

When accurately measuring, the proper alarm point for the gas detector should be determined after considering the temperature and humidity influence.



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Visit us at http://www.sunrom.com

Light Dependent Resistor - LDR

Two cadmium sulphide(cds) photoconductive cells with spectral responses similar to that of the human eye. The cell resistance falls with increasing light intensity. Applications include smoke detection, automatic lighting control, batch counting and burglar alarm systems.

Applications

Photoconductive cells are used in many different types of circuits and applications.

Analog Applications

- Camera Exposure Control
- Auto Slide Focus - dual cell
- Photocopy Machines - density of toner
- Colorimetric Test Equipment
- Densitometer
- Electronic Scales - dual cell
- Automatic Gain Control – modulated light source
- Automated Rear View Mirror

Digital Applications

- Automatic Headlight Dimmer
- Night Light Control
- Oil Burner Flame Out
- Street Light Control
- Absence / Presence (beam breaker)
- Position Sensor

Electrical Characteristics

Parameter	Conditions	Min	Typ	Max	Unit
Cell resistance	1000 LUX 10 LUX	- -	400 9	- -	Ohm K Ohm
Dark Resistance	-	-	1	-	M Ohm
Dark Capacitance	-	-	3.5	-	pF
Rise Time	1000 LUX 10 LUX	- -	2.8 18	- -	ms ms
Fall Time	1000 LUX 10 LUX	- -	48 120	- -	ms ms
Voltage AC/DC Peak		-	-	320	V max
Current		-	-	75	mA max
Power Dissipation				100	mW max
Operating Temperature		-60	-	+75	Deg. C

Guide to source illuminations

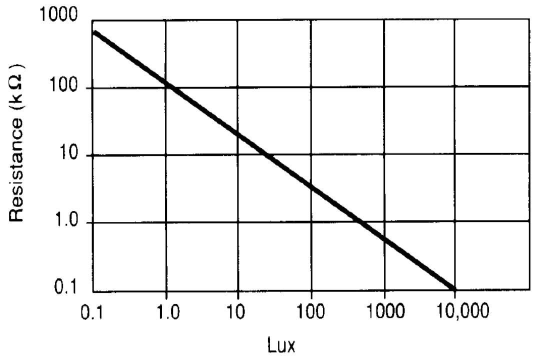
Light source Illumination	LUX
Moonlight	0.1
60W Bulb at 1m	50
1W MES Bulb at 0.1m	100
Fluorescent Lighting	500
Bright Sunlight	30,000

FIGURE 1 CIRCUIT SYMBOL

Sensitivity

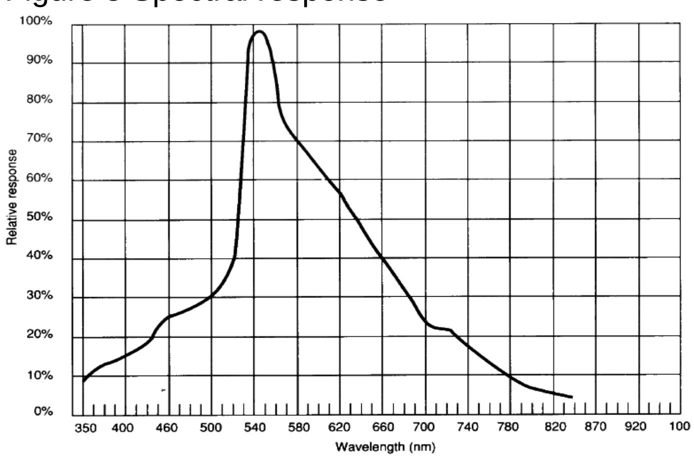
The sensitivity of a photodetector is the relationship between the light falling on the device and the resulting output signal. In the case of a photocell, one is dealing with the relationship between the incident light and the corresponding resistance of the cell.

FIGURE 2 RESISTANCE AS FUNCTION OF ILLUMINATION



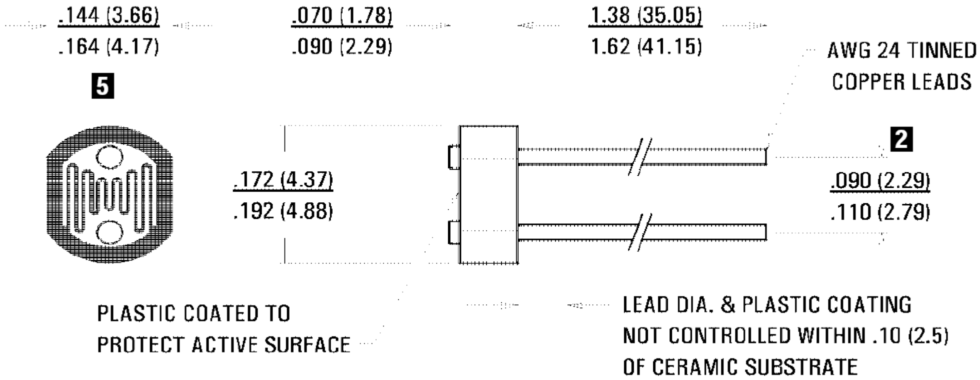
Spectral Response

Figure 3 Spectral response



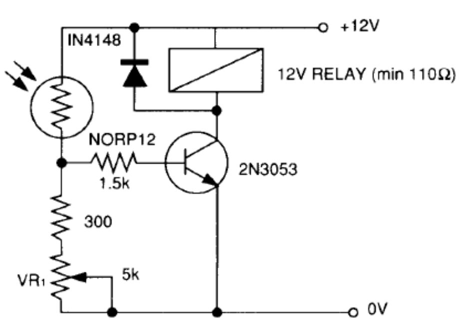
Like the human eye, the relative sensitivity of a photoconductive cell is dependent on the wavelength (color) of the incident light. Each photoconductor material type has its own unique spectral response curve or plot of the relative response of the photocell versus wavelength of light.

Dimensions



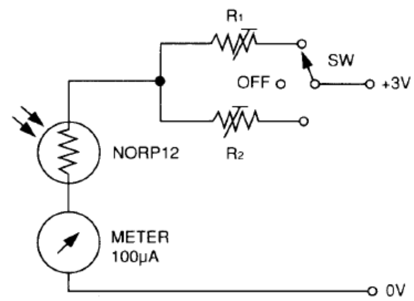
Typical Application Circuits

Figure 6 Sensitive light operated relay



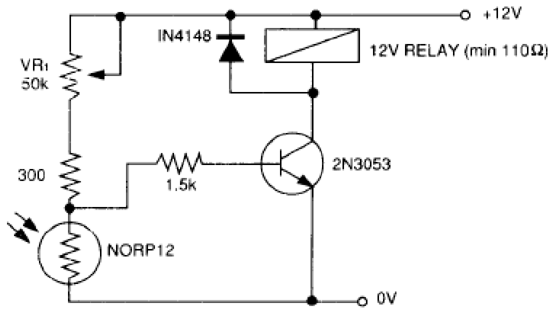
Relay energised when light level increases above the level set by VR_1

Figure 9 Logarithmic law photographic light meter



Typical value $R^1 = 100k\Omega$
$R^2 = 200k\Omega$ preset to give two overlapping ranges.
(Calibration should be made against an accurate meter.)

Figure 7 Light interruption detector



As Figure 6 relay energised when light level drops below the level set by VR_1

Figure 8 Automatic light circuit

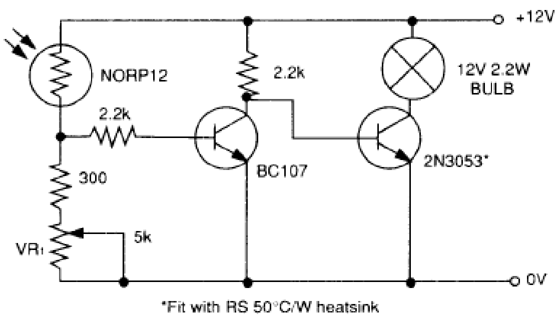
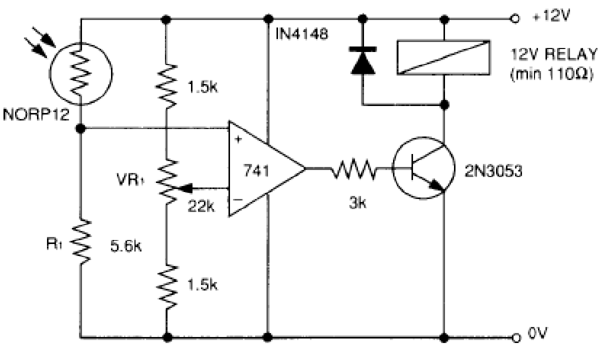
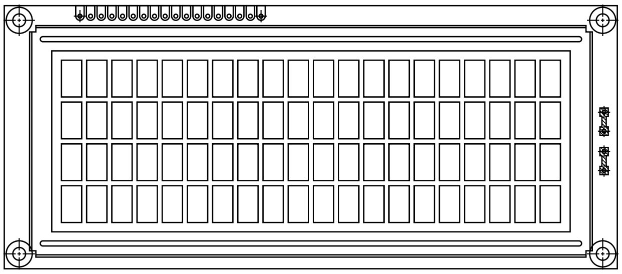


Figure 10 Extremely sensitive light operated relay



(Relay energised when light exceeds preset level.) Incorporates a balancing bridge and op-amp. R_1 and NORP12 may be interchanged for the reverse function.

20 x 4 Character LCD



FEATURES

- Type: Character
- Display format: 20 x 4 characters
- Built-in controller: ST 7066 (or equivalent)
- Duty cycle: 1/16
- 5 x 8 dots includes cursor
- + 5 V power supply (also available for + 3 V)
- LED can be driven by pin 1, pin 2, pin 15, pin 16 or A and K
- N.V. optional for + 3 V power supply
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

Pb-free
RoHS
COMPLIANT

MECHANICAL DATA

ITEM	STANDARD VALUE	UNIT
Module Dimension	146.0 x 62.5	mm
Viewing Area	123.5 x 43.0	
Dot Size	0.92 x 1.10	
Dot Pitch	0.98 x 1.16	
Mounting Hole	139.0 x 55.5	
Character Size	4.84 x 9.22	

ABSOLUTE MAXIMUM RATINGS

ITEM	SYMBOL	STANDARD VALUE			UNIT
		MIN.	TYP.	MAX.	
Power Supply	V_{DD} to V_{SS}	- 0.3	-	7.0	V
Input Voltage	V_I	- 0.3	-	V_{DD}	

Note

- V_{SS} = 0 V, V_{DD} = 5.0 V

ELECTRICAL CHARACTERISTICS

ITEM	SYMBOL	CONDITION	STANDARD VALUE			UNIT
			MIN.	TYP.	MAX.	
Input Voltage	V_{DD}	V_{DD} = + 5 V	4.7	5.0	5.3	V
		V_{DD} = + 3 V	2.7	3.0	5.3	
Supply Current	I_{DD}	V_{DD} = + 5 V	-	8.0	10.0	mA
Recommended LC Driving Voltage for Normal Temperature Version Module	V_{DD} to V_0	- 20 °C	5.0	5.1	5.7	V
		0 °C	4.6	4.8	5.2	
		25 °C	4.1	4.5	4.7	
		50 °C	3.9	4.2	4.5	
		70 °C	3.7	3.9	4.3	
LED Forward Voltage	V_F	25 °C	-	4.2	4.6	V
LED Forward Current	I_F	25 °C	-	540	1080	mA
EL Power Supply Current	I_{EL}	V_{EL} = 110 V_{AC}, 400 Hz	-	-	5.0	mA

OPTIONS

PROCESS COLOR						BACKLIGHT			
TN	STN Gray	STN Yellow	STN Blue	FSTN B&W	STN Color	None	LED	EL	CCFL
x	x	x	x	x		x	x	x	

For detailed information, please see the "Product Numbering System" document.

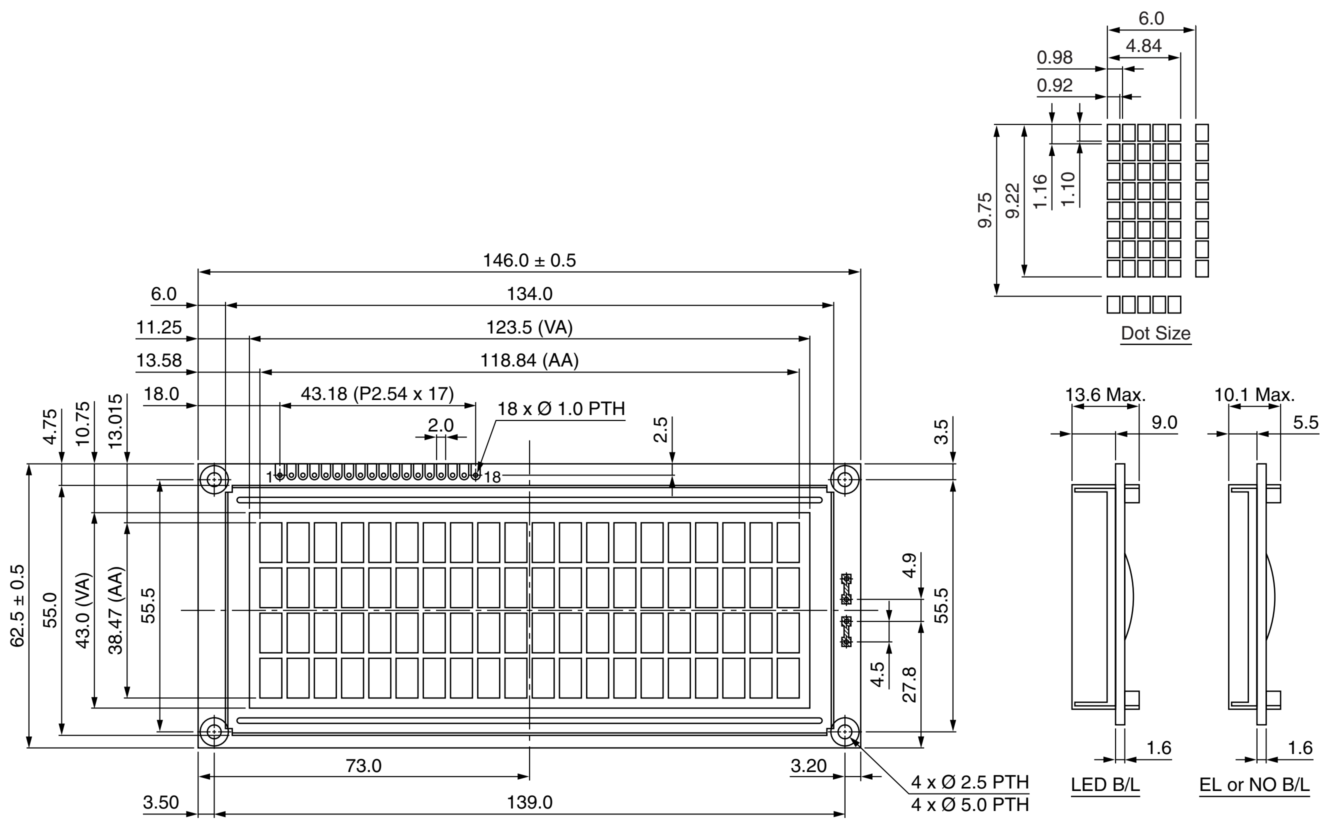
DISPLAY CHARACTER ADDRESS CODE

Display Position	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20
DD RAM Address	00	01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	0E	0F	10	11	12	13
DD RAM Address	40	41	42	43	44	45	46	47	48	49	4A	4B	4C	4D	4E	4F	50	51	52	53
DD RAM Address	14	15	16	17	18	19	1A	1B	1C	1D	1E	1F	20	21	22	23	24	25	26	27
DD RAM Address	54	55	56	57	58	59	5A	5B	5C	5D	5E	5F	60	61	62	63	64	65	66	67

For technical questions, contact: displays@vishay.com

INTERFACE PIN FUNCTION		
PIN NO.	SYMBOL	FUNCTION
1	V_{SS}	Ground
2	V_{DD}	+ 3 V or + 5 V
3	V_0	Contrast adjustment
4	RS	H/L register select signal
5	$R/\overline{W}$	H/L read/write signal
6	E	H → L enable signal
7	DB0	H/L data bus line
8	DB1	H/L data bus line
9	DB2	H/L data bus line
10	DB3	H/L data bus line
11	DB4	H/L data bus line
12	DB5	H/L data bus line
13	DB6	H/L data bus line
14	DB7	H/L data bus line
15	A	Power supply for LED (4.2 V)
16	K	Power supply for B/L (0 V)
17	NC/V_{EE}	NC or negative voltage output
18	NC	NC connection

DIMENSIONS in millimeters



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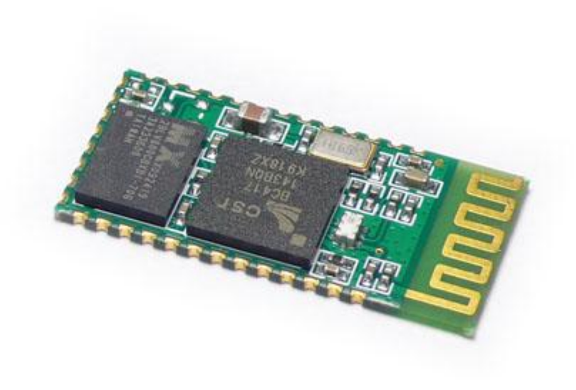
HC-05

-Bluetooth to Serial Port Module

Overview



HC-05 module is an easy to use Bluetooth SPP (Serial Port Protocol) module, designed for transparent wireless serial connection setup.
Serial port Bluetooth module is fully qualified Bluetooth V2.0+EDR (Enhanced Data Rate) 3Mbps Modulation with complete 2.4GHz radio transceiver and baseband. It uses CSR Bluecore 04-External single chip Bluetooth system with CMOS technology and with AFH(Adaptive Frequency Hopping Feature). It has the footprint as small as 12.7mmx27mm. Hope it will simplify your overall design/development cycle.

Specifications

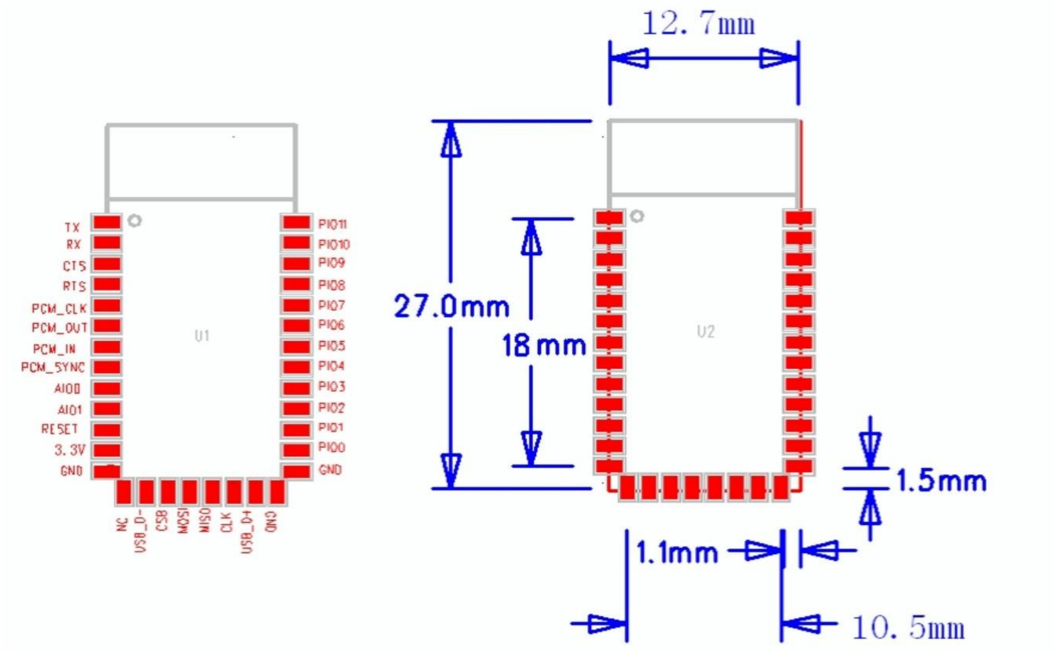
Hardware features

- Typical -80dBm sensitivity
- Up to +4dBm RF transmit power
- Low Power 1.8V Operation ,1.8 to 3.6V I/O
- PIO control
- UART interface with programmable baud rate
- With integrated antenna
- With edge connector

Software features

- Default Baud rate: 38400, Data bits:8, Stop bit:1,Parity:No parity, Data control: has. Supported baud rate: 9600,19200,38400,57600,115200,230400,460800.
- Given a rising pulse in PIO0, device will be disconnected.
- Status instruction port PIO1: low-disconnected, high-connected;
- PIO10 and PIO11 can be connected to red and blue led separately. When master and slave are paired, red and blue led blinks 1time/2s in interval, while disconnected only blue led blinks 2times/s.
- Auto-connect to the last device on power as default.
- Permit pairing device to connect as default.
- Auto-pairing PINCODE:"0000" as default
- Auto-reconnect in 30 min when disconnected as a result of beyond the range of connection.

Hardware



PIN Name	PIN #	Pad type	Description	Note
GND	13 21 22	VSS	Ground pot	
3.3 VCC	12	3.3V	Integrated 3.3V (+) supply with On-chip linear regulator output within 3.15-3.3V	
AIO0	9	Bi-Directional	Programmable input/output line	
AIO1	10	Bi-Directional	Programmable input/output line	
PIO0	23	Bi-Directional RX EN	Programmable input/output line, control output for LNA(if fitted)	
PIO1	24	Bi-Directional TX EN	Programmable input/output line, control output for PA(if fitted)	
PIO2	25	Bi-Directional	Programmable input/output line	
PIO3	26	Bi-Directional	Programmable input/output line	
PIO4	27	Bi-Directional	Programmable input/output line	
PIO5	28	Bi-Directional	Programmable input/output line	
PIO6	29	Bi-Directional	Programmable input/output line	
PIO7	30	Bi-Directional	Programmable input/output line	
PIO8	31	Bi-Directional	Programmable input/output line	
PIO9	32	Bi-Directional	Programmable input/output line	
PIO10	33	Bi-Directional	Programmable input/output line	
PIO11	34	Bi-Directional	Programmable input/output line	

RESETB	**11**	CMOS input with weak internal pull-up	Reset if low.input debouncde so must be low for >5MS to cause a reset	
UART_RTS	**4**	**CMOS output, tri-stable with weak internal pull-up**	**UART request to send, active low**	
UART_CTS	**3**	**CMOS input with weak internal pull-down**	**UART clear to send, active low**	
UART_RX	**2**	**CMOS input with weak internal pull-down**	**UART Data input**	
UART_TX	**1**	**CMOS output, Tri-stable with weak internal pull-up**	**UART Data output**	
SPI_MOSI	**17**	**CMOS input with weak internal pull-down**	**Serial peripheral interface data input**	
SPI_CSB	**16**	**CMOS input with weak internal pull-up**	**Chip select for serial peripheral interface, active low**	
SPI_CLK	**19**	**CMOS input with weak internal pull-down**	**Serial peripheral interface clock**	
SPI_MISO	**18**	**CMOS input with weak internal pull-down**	**Serial peripheral interface data Output**	
USB_-	**15**	**Bi-Directional**		

USB_+	20	Bi-Directional		
NC	14			
PCM_CLK	5	Bi-Directional	Synchronous PCM data clock	
PCM_OUT	6	CMOS output	Synchronous PCM data output	
PCM_IN	7	CMOS Input	Synchronous PCM data input	
PCM_SYNC	8	Bi-Directional	Synchronous PCM data strobe	

AT command Default:

How to set the mode to server (master):

1. Connect PIO11 to high level.
2. Power on, module into command state.
3. Using baud rate 38400, sent the "AT+ROLE=1\r\n" to module, with "OK\r\n" means setting successes.
4. Connect the PIO11 to low level, repower the module, the module work as server (master).

AT commands: (all end with \r\n)

1. Test command:

Command	Respond	Parameter
AT	OK	-

2. Reset

Command	Respond	Parameter
AT+RESET	OK	-

3. Get firmware version

Command	Respond	Parameter
AT+VERSION?	+VERSION:<Param> OK	Param : firmware version

Example:

AT+VERSION?\r\n

+VERSION:2.0-20100601

OK

4. Restore default

Command	Respond	Parameter
AT+ORGL	OK	-

Default state:

Slave mode, pin code :1234, device name: H-C-2010-06-01 ,Baud 38400bits/s.

5. Get module address

Command	Respond	Parameter
AT+ADDR?	+ADDR:<Param> OK	Param: address of Bluetooth module

Bluetooth address: NAP: UAP : LAP

Example:

AT+ADDR?\r\n

+ADDR:1234:56:abcdef

OK

6. Set/Check module name:

Command	Respond	Parameter
AT+NAME=<Param>	OK	Param: Bluetooth module name (Default :HC-05)
AT+NAME?	+NAME:<Param> OK (/FAIL)	

Example:

AT+NAME=HC-05\r\n set the module name to “HC-05”

OK

AT+NAME=ITeadStudio\r\n

OK

AT+NAME?\r\n

+NAME: ITeadStudio

OK

7. Get the Bluetooth device name:

Command	Respond	Parameter
AT+RNAME?<Param1>	1. +NAME:<Param2> OK 2. FAIL	Param1,Param 2 : the address of Bluetooth device

Example: (Device address 00:02:72:od:22:24， name： ITead)

AT+RNAME? 0002，72，od2224\r\n

+RNAME:ITead

OK

8. Set/Check module mode:

Command	Respond	Parameter
AT+ROLE=<Param>	OK	Param: 0- Slave
AT+ ROLE?	+ROLE:<Param>	

	OK	1-Master 2-Slave-Loop

9. Set/Check device class

Command	Respond	Parameter
AT+CLASS=<Param>	OK	Param: Device Class
AT+ CLASS?	1. +CLASS:<Param> OK 2. FAIL	

10. Set/Check GIAC (General Inquire Access Code)

Command	Respond	Parameter
AT+IAC=<Param>	1.OK 2. FAIL	Param: GIAC (Default : 9e8b33)
AT+IAC	+IAC:<Param> OK	

Example:
AT+IAC=9e8b3f\r\n
OK
AT+IAC?\r\n
+IAC: 9e8b3f
OK

11. Set/Check -- Query access patterns

Command	Respond	Parameter
AT+INQM=<Param>,<Param2>, <Param3>	1.OK 2. FAIL	Param: 0——inquiry_mode_standard 1——inquiry_mode_rssi Param2: Maximum number of Bluetooth devices to respond to Param3: Timeout (1-48 : 1.28s to 61.44s)
AT+ INQM?	+INQM： <Param>,<Param2>, <Param3> OK	

Example:
AT+INQM=1,9,48\r\n
OK
AT+INQM\r\n
+INQM:1, 9, 48
OK

12. Set/Check PIN code:

Command	Respond	Parameter
AT+PSWD=<Param>	OK	Param: PIN code (Default 1234)
AT+ PSWD?	+ PSWD ： <Param> OK	

13. Set/Check serial parameter:

Command	Respond	Parameter
AT+UART=<Param>,<Param2>,<Param3>	OK	Param1: Baud Param2: Stop bit Param3: Parity
AT+ UART?	+UART=<Param>,<Param2>, <Param3> OK	

Example:

AT+UART=115200， 1,2,\r\n

OK

AT+UART?

+UART:115200,1,2

OK

14. Set/Check connect mode:

Command	Respond	Parameter
AT+CMODE=<Param>	OK	Param: 0 - connect fixed address 1 - connect any address 2 - slave-Loop
AT+ CMODE?	+ CMODE:<Param> OK	

15. Set/Check fixed address:

Command	Respond	Parameter
AT+BIND=<Param>	OK	Param: Fixed address (Default 00:00:00:00:00:00)
AT+ BIND?	+ BIND:<Param> OK	

Example:

AT+BIND=1234， 56， abcdef\r\n

OK

AT+BIND?\r\n

+BIND:1234:56:abcdef

OK

16. Set/Check LED I/O

Command	Respond	Parameter
AT+POLAR=<Param1,<Param2>	OK	Param1: 0- PIO8 low drive LED 1- PIO8 high drive LED
AT+ POLAR?	+ POLAR=<Param1>,<Param2> OK	

		Param2: 0- PIO9 low drive LED 1- PIO9 high drive LED

17. Set PIO output

Command	Respond	Parameter
AT+PIO=<Param1>,<Param2>	OK	Param1: PIO number Param2: PIO level 0- low 1- high

Example:

1. PIO10 output high level

AT+PI0=10，1\r\n

OK

18. Set/Check – scan parameter

Command	Respond	Parameter
AT+IPSCAN=<Param1>,<Param2>,<Param3>,<Param4>	OK	Param1: Query time interval Param2：Query duration Param3：Paging interval Param4：Call duration
AT+IPSCAN?	+IPSCAN:<Param1>,<Param2>,<Param3>,<Param4> OK	

Example:

AT+IPSCAN =1234,500,1200,250\r\n

OK

AT+IPSCAN?

+IPSCAN:1234,500,1200,250

19. Set/Check – SHIFF parameter

Command	Respond	Parameter
AT+SNIFF=<Param1>,<Param2>,<Param3>,<Param4>	OK	Param1: Max time Param2: Min time Param3: Retry time Param4: Time out
AT+ SNIFF?	+SNIFF:<Param1>,<Param2>,<Param3>,<Param4> OK	

20. Set/Check security mode

Command	Respond	Parameter
AT+SENM=<Param1>,<Param2>	1. OK 2. FAIL	Param1: 0——sec_mode0+off 1——sec_mode1+non_se
AT+ SENM?	+ SENM:<Param1>,<Param2>	

	OK	cure 2——sec_mode2_service 3——sec_mode3_link 4——sec_mode_unknow n Param2: 0——hci_enc_mode_off 1——hci_enc_mode_pt_t o_pt 2——hci_enc_mode_pt_t o_pt_and_bcast

21. Delete Authenticated Device

Command	Respond	Parameter
AT+PMSAD=<Param>	OK	Param: Authenticated Device Address

Example:
AT+PMSAD =1234,56,abcdef\r\n
OK

22. Delete All Authenticated Device

Command	Respond	Parameter
AT+ RMAAD	OK	-

23. Search Authenticated Device

Command	Respond	Parameter
AT+FSAD=<Param>	1. OK 2. FAIL	Param: Device address

24. Get Authenticated Device Count

Command	Respond	Parameter
AT+ADCN?	+ADCN：<Param> OK	Param: Device Count

25. Most Recently Used Authenticated Device

Command	Respond	Parameter
AT+MRAD?	+ MRAD：<Param> OK	Param: Recently Authenticated Device Address

26. Get the module working state

Command	Respond	Parameter

AT+ STATE?	+ STATE： <Param> OK	Param: “INITIALIZED” “READY” “PAIRABLE” “PAIRED” “INQUIRING” “CONNECTING” “CONNECTED” “DISCONNECTED” “NUKNOW”

27. Initialize the SPP profile lib

Command	Respond	Parameter
AT+INIT	1. OK 2. FAIL	-

28. Inquiry Bluetooth Device

Command	Respond	Parameter
AT+INQ	+INQ: <Param1>, <Param2>, <Param3> …. OK	Param1：Address Param2：Device Class Param3 ： RSSI Signal strength

Example:

AT+INIT\r\n
OK
AT+IAC=9e8b33\r\n
OK
AT+CLASS=0\r\n
AT+INQM=1,9,48\r\n
At+INQ\r\n
+INQ:2:72:D2224,3E0104,FFBC
+INQ:1234:56:0,1F1F,FFC1
+INQ:1234:56:0,1F1F,FFC0
+INQ:1234:56:0,1F1F,FFC1
+INQ:2:72:D2224,3F0104,FFAD
+INQ:1234:56:0,1F1F,FFBE
+INQ:1234:56:0,1F1F,FFC2
+INQ:1234:56:0,1F1F,FFBE
+INQ:2:72:D2224,3F0104,FFBC
OK

28. Cancel Inquiring Bluetooth Device

Command	Respond	Parameter
AT+ INQC	OK	-

29. Equipment Matching

Command	Respond	Parameter
AT+PAIR=<Param1>,<Param2>	1. OK 2. FAIL	Param1：Device Address Param2：Time out

30. Connect Device

Command	Respond	Parameter
AT+LINK=<Param>	1. OK 2. FAIL	Param：Device Address

Example:
AT+FSAD=1234,56,abcdef\r\n
OK
AT+LINK=1234,56,abcdef\r\n
OK

31. Disconnect

Command	Respond	Parameter
AT+DISC	1. +DISC:SUCCESS OK 2. +DISC:LINK_LOSS OK 3. +DISC:NO_SLC OK 4. +DISC:TIMEOUT OK 5. +DISC:ERROR OK	Param：Device Address

32. Energy-saving mode

Command	Respond	Parameter
AT+ENSNIFF=<Param>	OK	Param：Device Address

33. Exerts Energy-saving mode

Command	Respond	Parameter
AT+ EXSNIFF =<Param>	OK	Param：Device Address

Revision History

Rev.	Description	Release date
v1.0	Initial version	7/18/2010